

Semiconductor Detectors

applications in basic science and industry

OUTLINE Part II

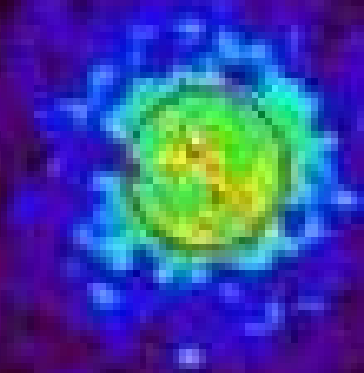
1. Semiconductors based on sideward depletion

(a) the SDD with integrated FET

(b) the pnCCD

(c) the CDD

(d) the DEPFET (active pixel sensor)



2. Avalanche amplifiers

3. Summary and Conclusion

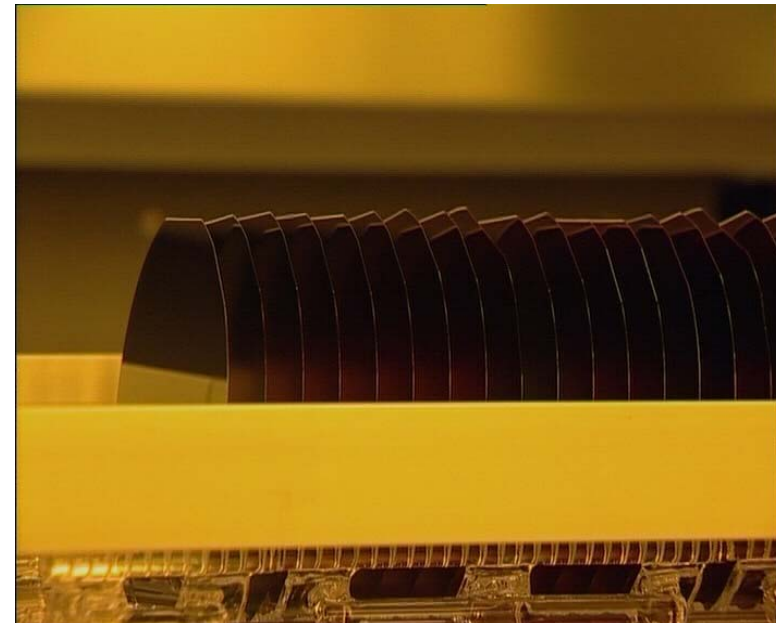
1. Semiconductors: $E_{\text{Gap}} \approx 1 - 3 \text{ eV}$
 - small leakage currents
 - low noise, operation @ r.t.
2. Pair creation energy: $w = 2 - 5 \text{ eV}$
 - large number of signal charges per energy deposit in detector
3. Density: $\rho = 2 - 10 \text{ g cm}^{-3}$
 - high energy loss per unit length
 - low range of δ - electrons

This leads to:

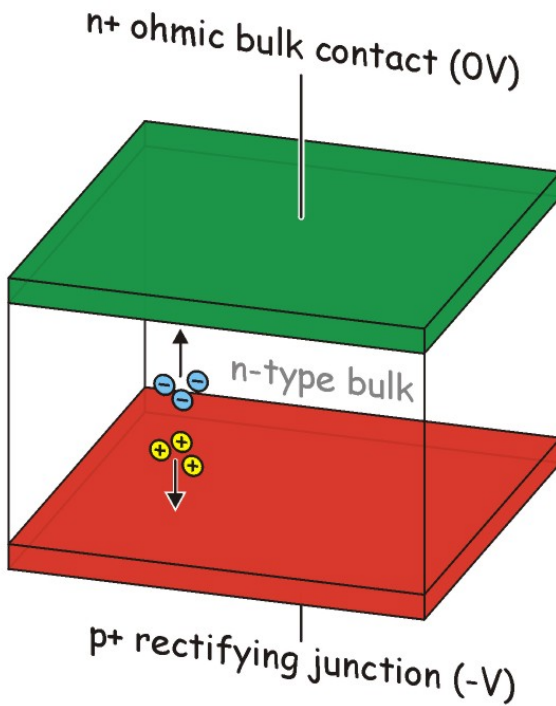
good energy resolution
high spatial resolution
high quantum and detection efficiency
good mechanical rigidity and thermal conductivity

Semiconductors equally offer:

fixed space charges
high mobility of charge carriers



Problem with planar diodes



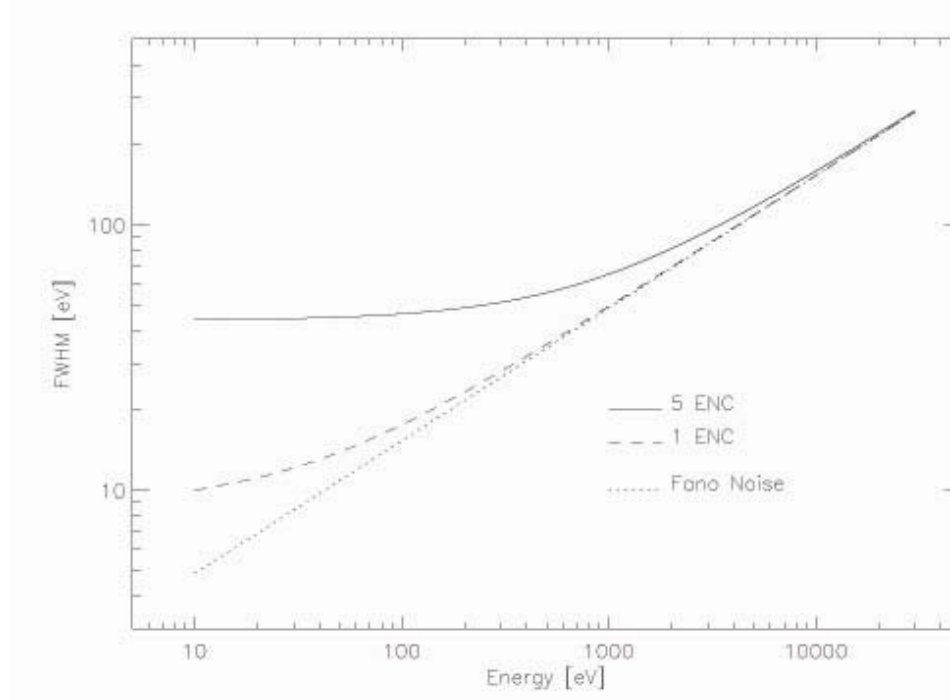
electronic noise

$$ENC = \sqrt{\underbrace{\alpha \frac{2kT}{g_m} C_{tot}^2 A_1 \frac{1}{T}}_{\text{thermal noise}} + \underbrace{2\pi\alpha_f C_{tot}^2 A_2}_{1/f \text{ noise}} + \underbrace{qI_L A_3 \tau}_{\text{leakage}}}$$

optimum shaping time

$$T_{opt} = \sqrt{\frac{2A_3}{A_1} \frac{kT}{q} \frac{C_{tot}^2}{I_L} \frac{2}{3g_m}}$$

- » For
 - good resolution
 - high count rate capability
- the total capacitance must be minimised!!

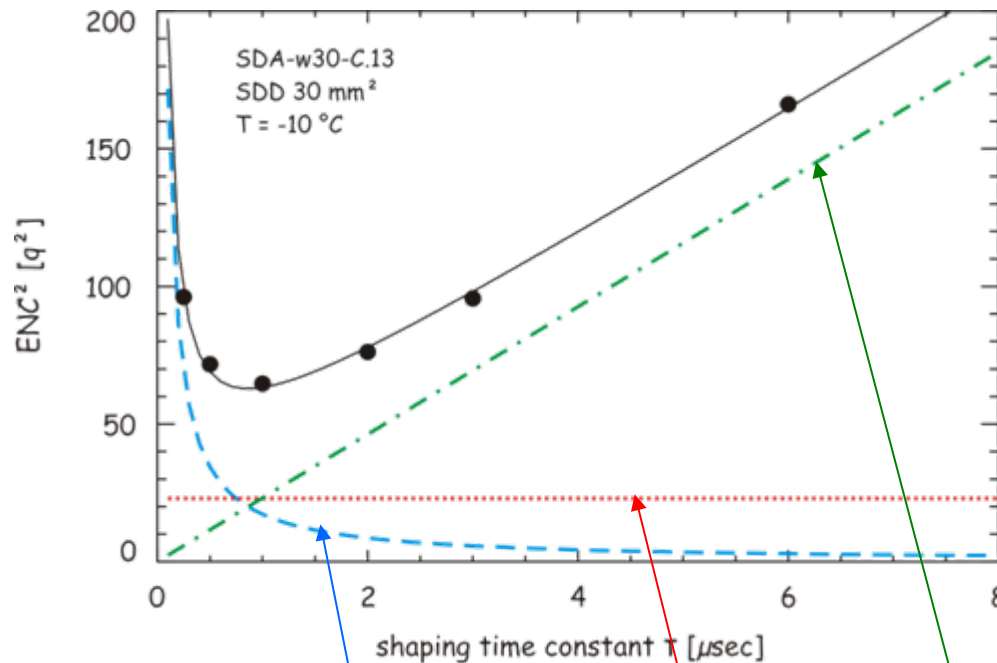


$$ENC_{\text{fano}}^2 = \frac{F \cdot E}{w}$$

$$ENC_{\text{trans}}^2 \approx (1 - \text{CTE}) N_{\text{trans}}$$

$$ENC^2 = \left(\alpha \frac{2kT}{g_m} C_{\text{tot}}^2 A_1 \right) \frac{1}{\tau} + \left[\left(2\pi a_f C_{\text{tot}}^2 + \frac{b_f}{2\pi} \right) A_2 \right] + \left(qI_l + \frac{2kT}{R_f} A_3 \right) \tau$$

$$ENC_{\text{tot}}^2 = ENC_{\text{el}}^2 + ENC_{\text{fano}}^2 + ENC_{\text{trans}}^2 + \dots$$



multi-parameter fit

» extraction of

- total capacitance C_{tot}
- 1/f noise coeff. a_f
- leakage current I_L

independent measurement of

- transconductance g_m
(180 ... 250 μS)

A_i = filter constants
(Gaussian 6th order)

τ = shaping time constant

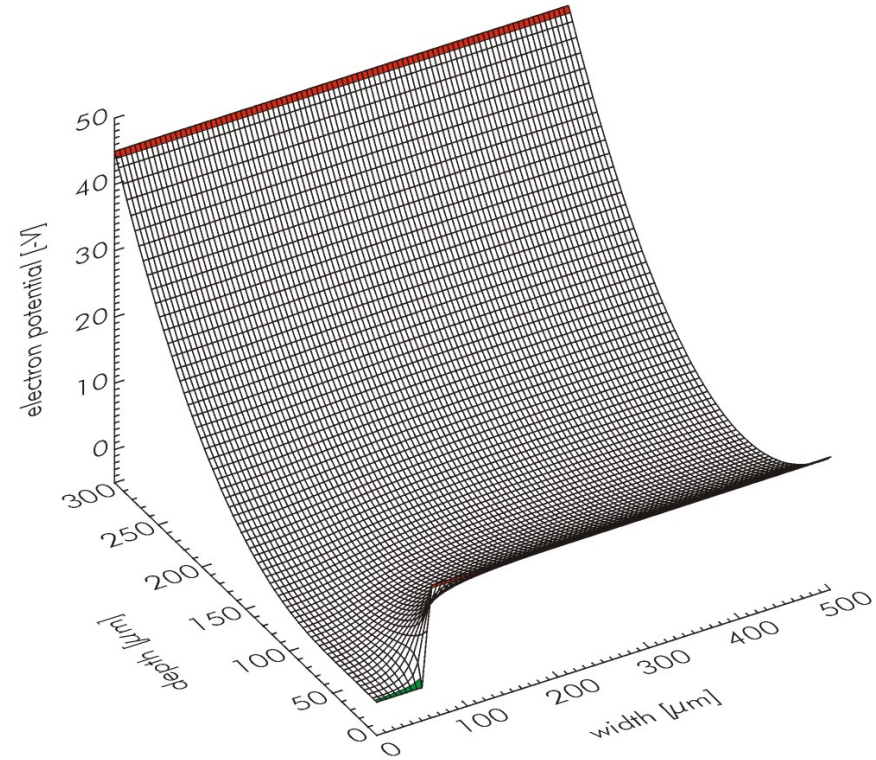
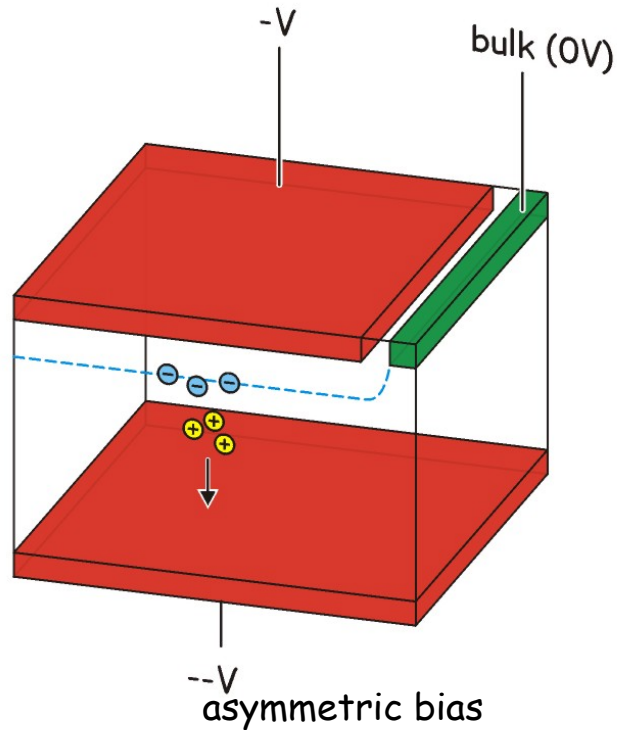
q = electron charge

a = 2/3 for FET in saturation

$$ENC^2 = \underbrace{\alpha \frac{2kT}{g_m} C_{\text{tot}}^2 A_1 \frac{1}{\tau}}_{\text{thermal noise}} + \underbrace{2\pi a_f C_{\text{tot}}^2 A_2}_{1/f \text{ noise}} + \underbrace{q I_L A_3 \tau}_{\text{leakage current}}$$

Sideward Depletion Structure

Emilio Gatti & Pavel Rehak, 1984

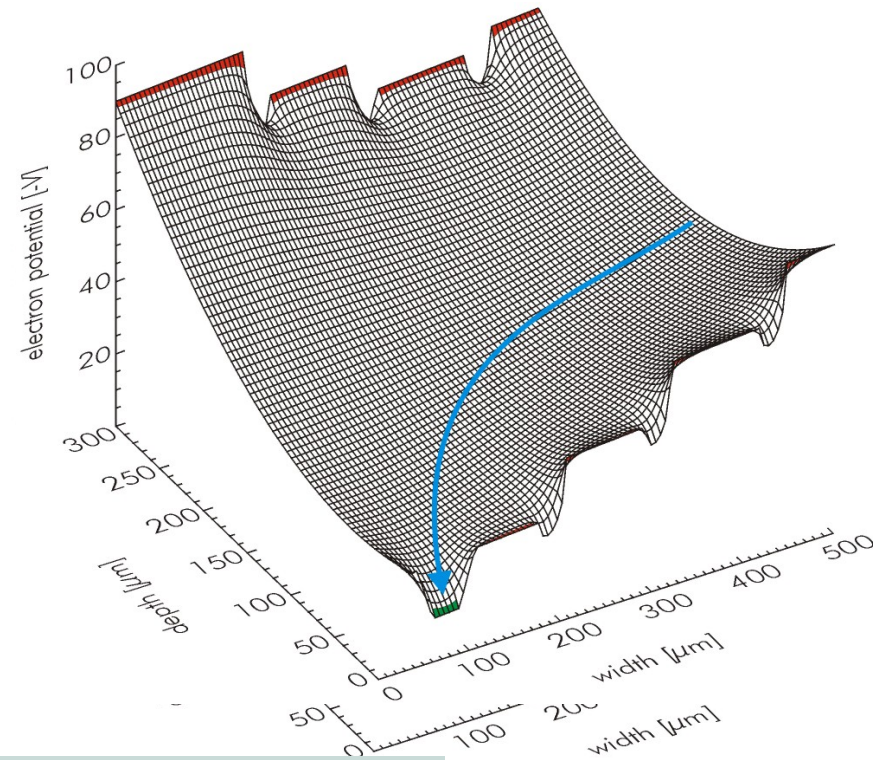
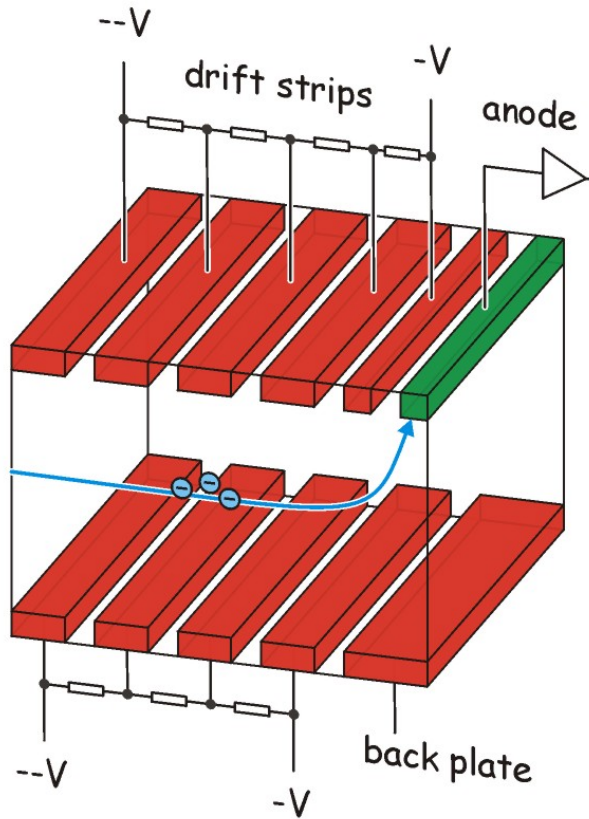


- fully depleted volume
- minimum capacitance of bulk contact (independent of sensitive area)

?? signal extraction ??

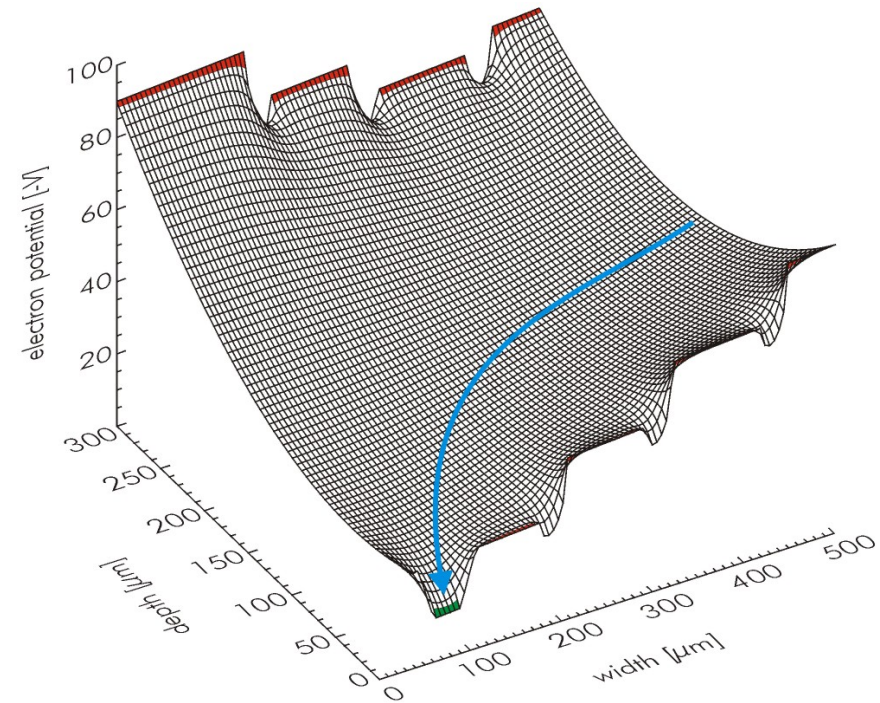
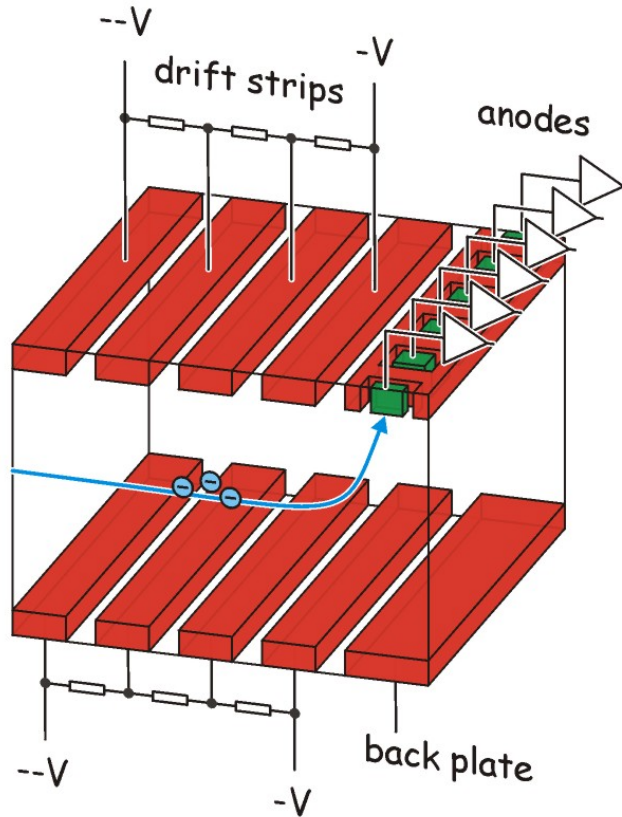
» advanced detector concepts

Silicon Drift Detector (SDD)



- drift field \parallel surface
- 1D position resolution by drift time measurement
start trigger!!

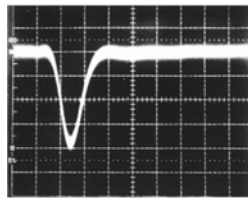
Silicon Drift Detector (SDD)



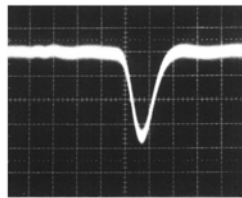
2D position resolution by

- drift time measurement
- segmentation of the anode

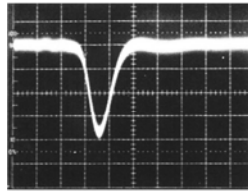
Signal for varying distance



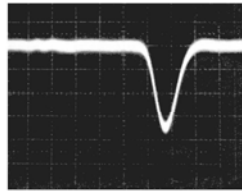
$d = 0.25 \text{ mm}$



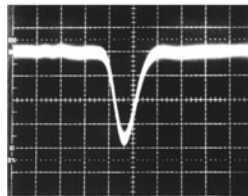
$d = 2.50 \text{ mm}$



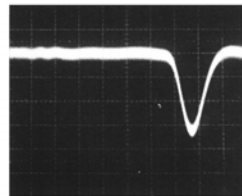
$d = 1.00 \text{ mm}$



$d = 3.25 \text{ mm}$



$d = 1.75 \text{ mm}$



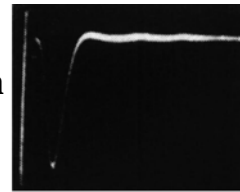
$d = 3.85 \text{ mm}$

Light pulser 22000e

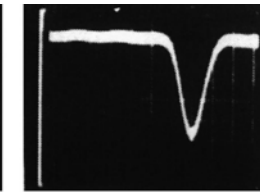
200 ns/div

for varying drift field

425 V/cm



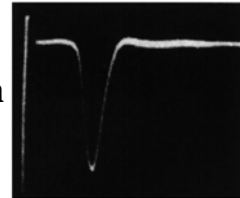
a



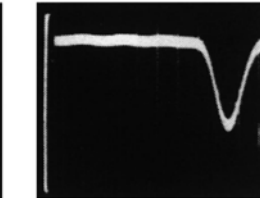
130 V/cm

e

265 V/cm



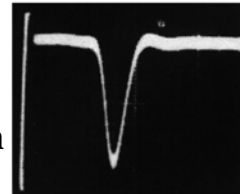
b



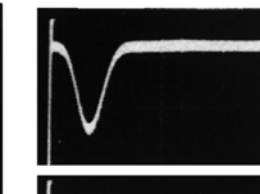
105 V/cm

f

210 V/cm



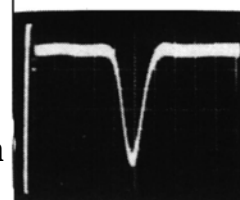
c



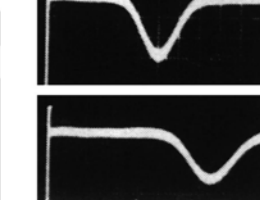
105 V/cm

g

185 V/cm



d



80 V/cm

h

67 V/cm

i

Light pulser 22000e

Integrated electronics on high resistivity Silicon



$$ENC^2 = \left(\alpha \frac{2kT}{gm} C^2_{tot} A_1 \right) \frac{1}{\tau} +$$

serial noise

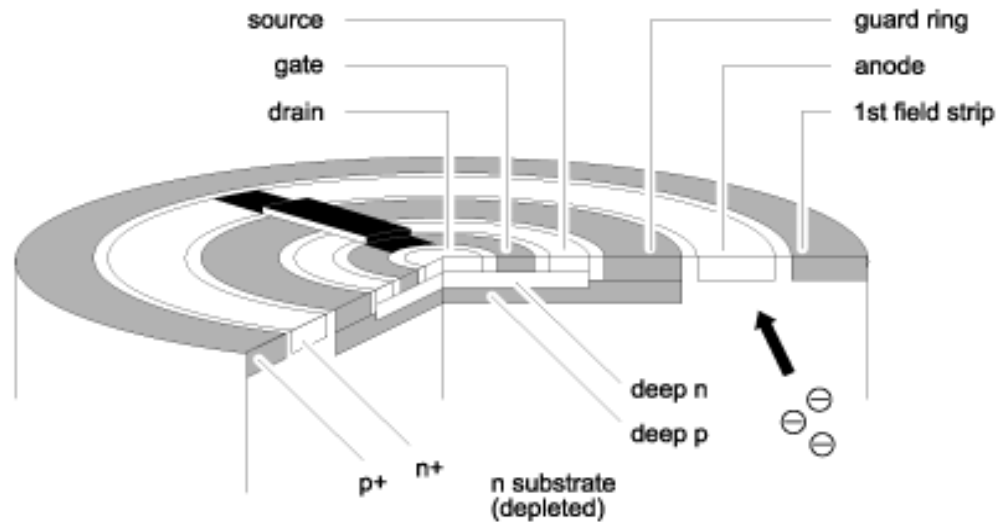
$$+ \left[\left(2\pi\alpha_f C^2_{tot} + \frac{b_f}{2\pi} \right) A_2 \right] +$$

low frequency noise (e.g. 1/f)

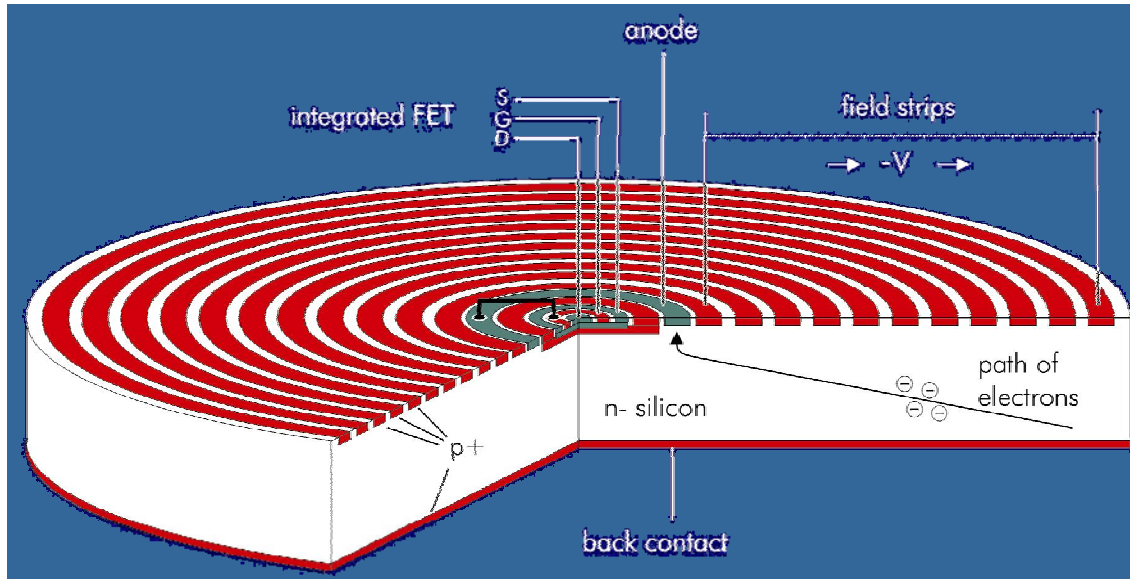
$$+ \left(qI_l + \frac{2kT}{R_f} A_3 \right) \tau$$

parallel noise

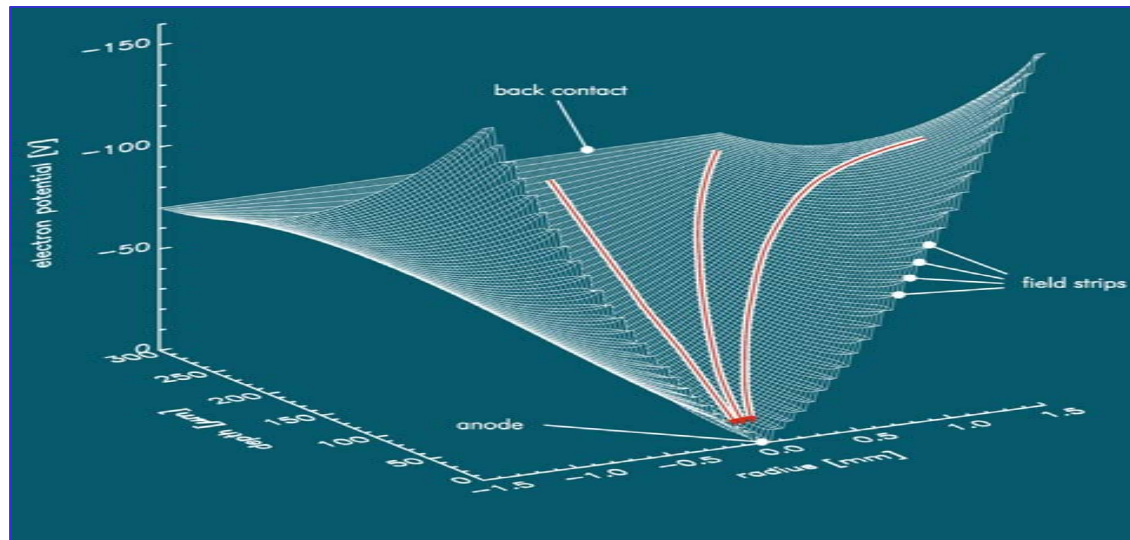
because of $Q = C \cdot U$
 $\Delta U = \Delta Q / C$



SDDs for astrophysics and industrial applications



SDD with integrated SSJFET

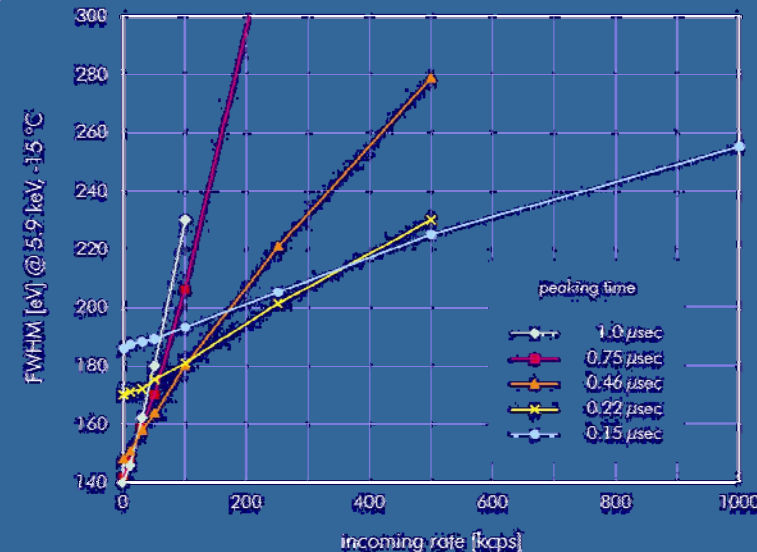
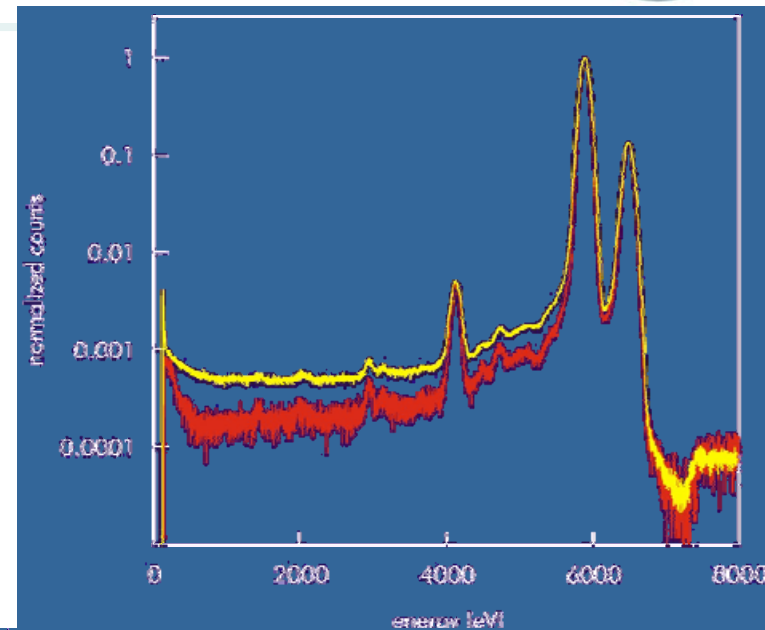
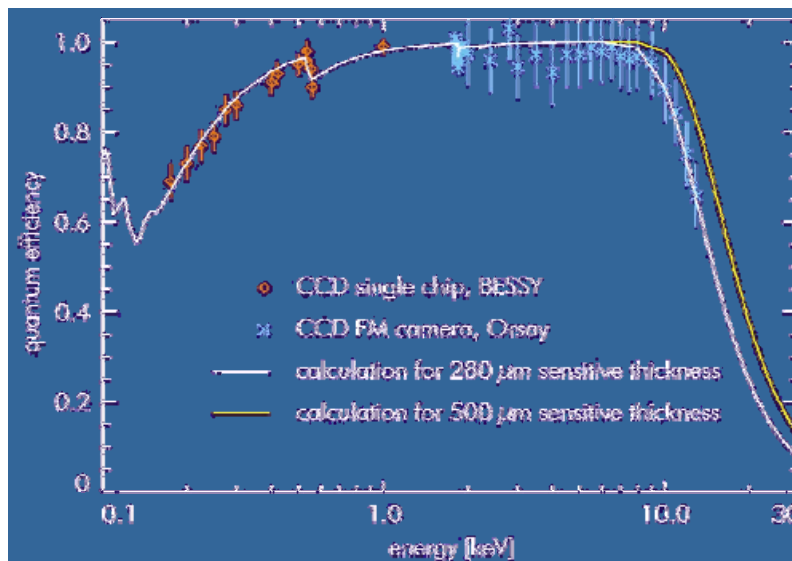


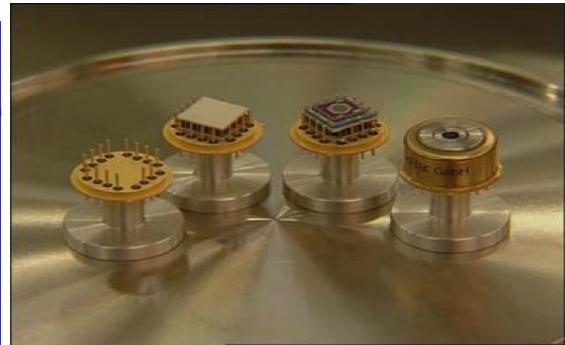
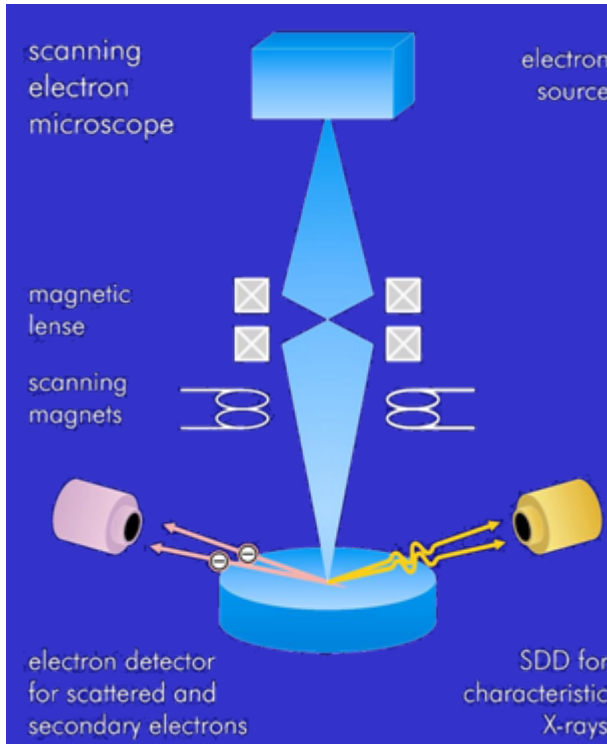
Electrical Potential in a circular SDD

SDD properties



- Energy resolution: $\Delta E_{FWHM} = 125 \text{ eV}$
- Count rate capability: up to 10^6 cps
- Peak/Background $\approx 10.000 : 1$
- Quantum efficiency: $> 90\%$ @ 0.3-10 keV
- Rad. hardness: $> 10^{14} \text{ Mo}_K \text{ Photonen}$
- Operating temperature: $T \approx -10^\circ \text{ C}$
- Random shape and size
- Triggersignal: $\Delta t \approx 3 - 5 \text{ ns}$
- Antireflective coating



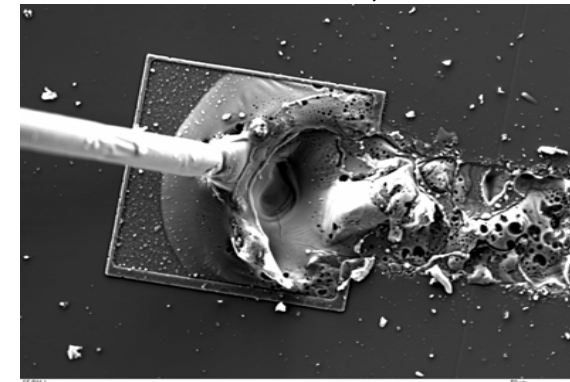


SDD – Modules from 5 mm² bis 100 mm², 1 – 61 Module/Chip

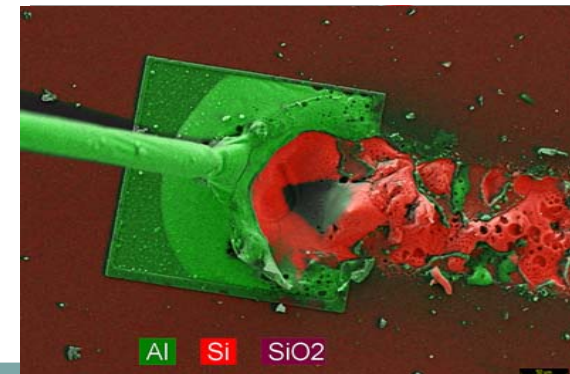
Measurements made by RÖNTEC, Berlin

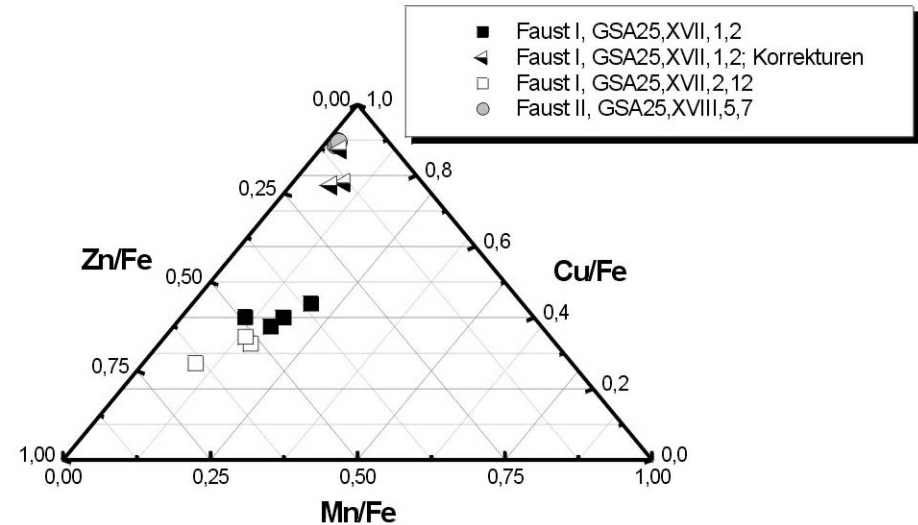
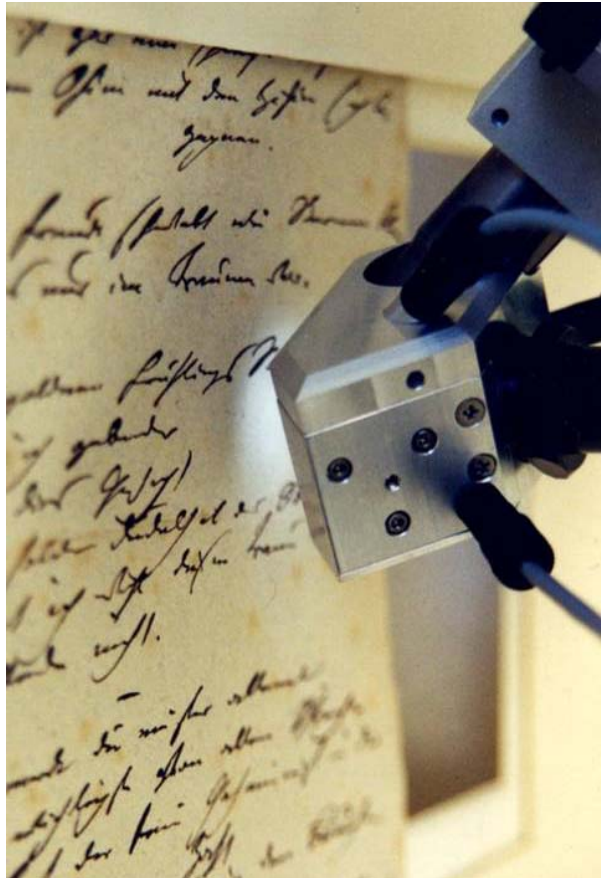
Scanning electron microscope with separated electron and X-ray detector

SEM – image



“colour – image”





"fingerprint" of Goethe's ink

⇒ editing of Faust I during Faust II work

experiment & figures by O. Hahn (BAM, Berlin)
with portable system "artTAX" (RÖNTEC)



mission profile

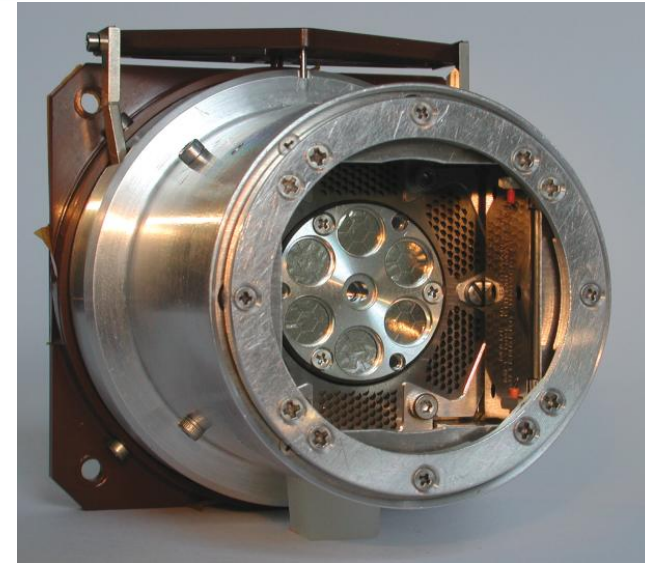
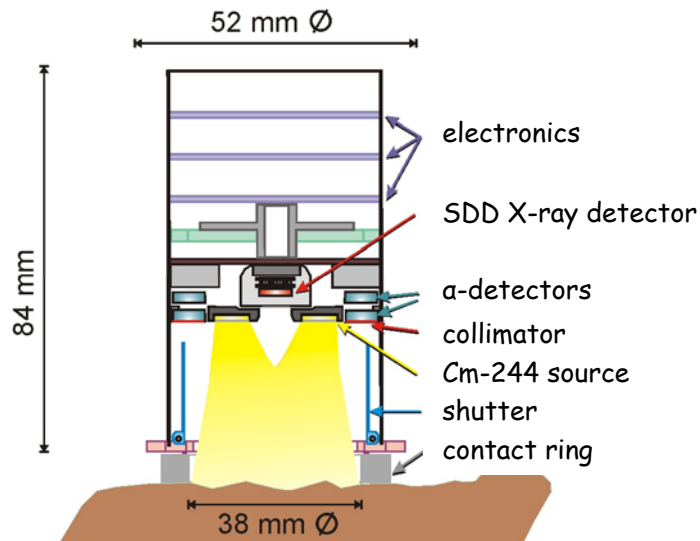
- 2 independent mobile landers
"Spirit" & "Opportunity"
- arrived 04./25.01.04
- scheduled for 3 months / 600 m
but still active

mission goals

- find traces of water
- investigate the geology of Mars
- prepare manned mission

PI of APXS system: R. Rieder
MPI für Chemie, Mainz

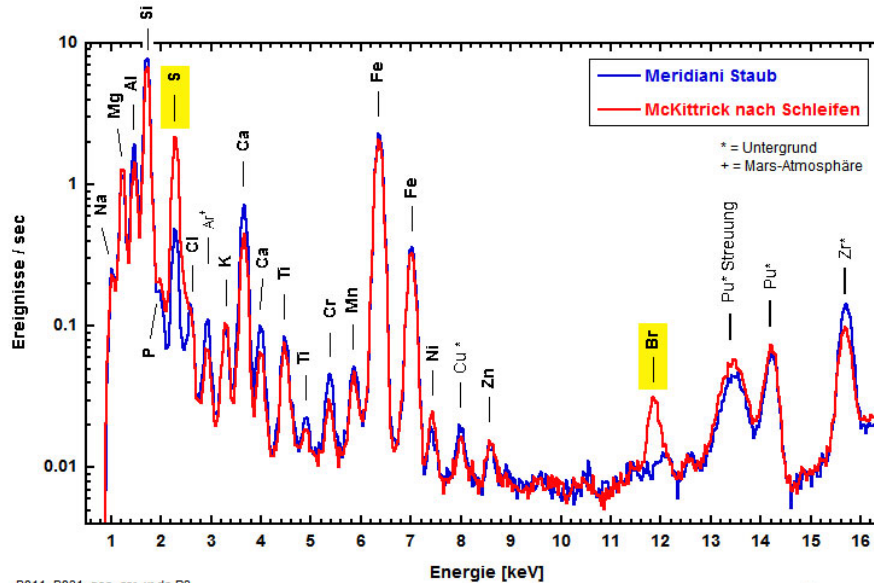
APXS (Alpha Particle X-ray Spectrometer)



- Curium-244 α - and X-ray sources
- Silicon Drift Detector
 - » PIXE, XRF
- α -particle detectors
 - » Rutherford backscattering

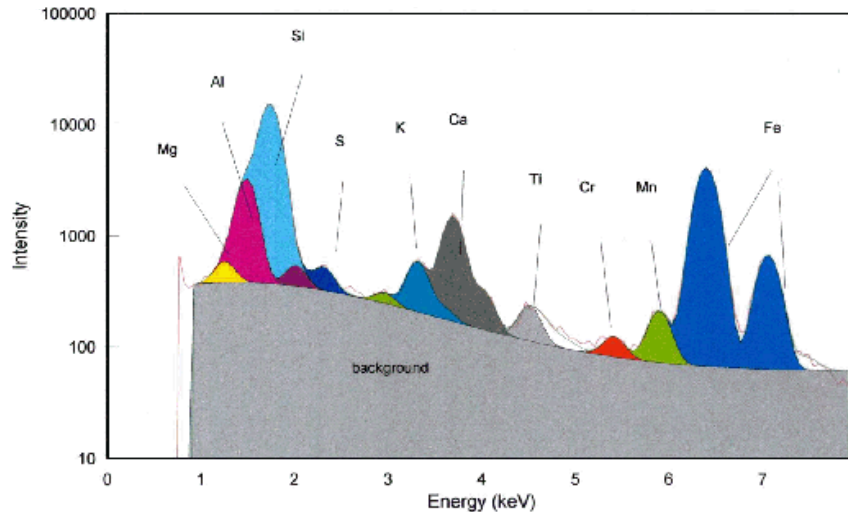


similar system on board of the ROSETTA comet lander



B011_B031_geo_coor_xr_de P3

© MPCh Mainz



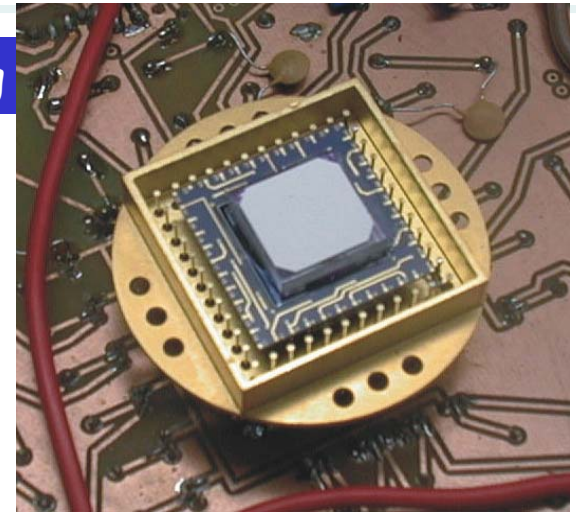
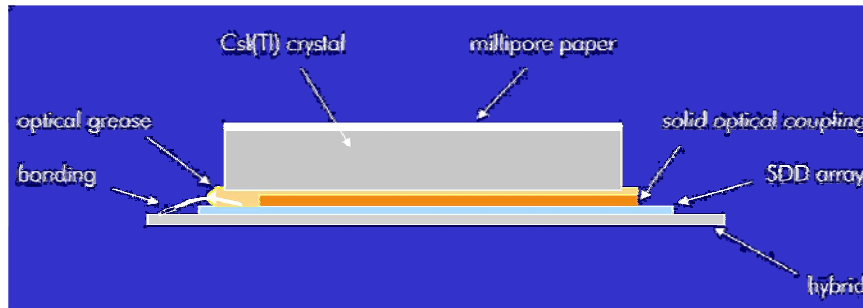
SDD

X-ray spectra of
Marsian samples
(2004)

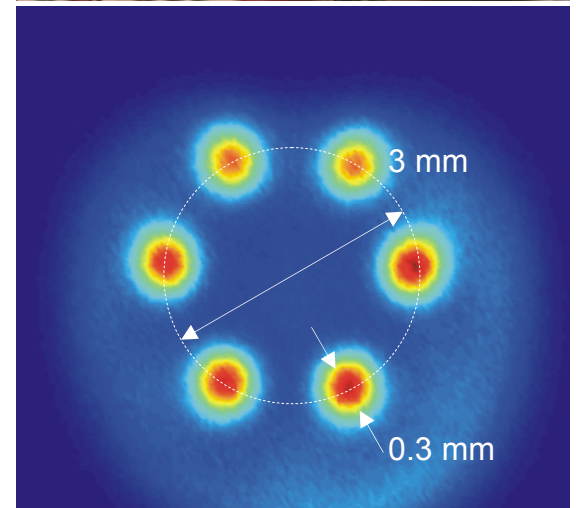
for comparison:

X-ray spectrum of Marsian
sample
by Pathfinder mission (1997)
equipped with **PIN-diode**

scintillator readout, medical γ -ray imaging

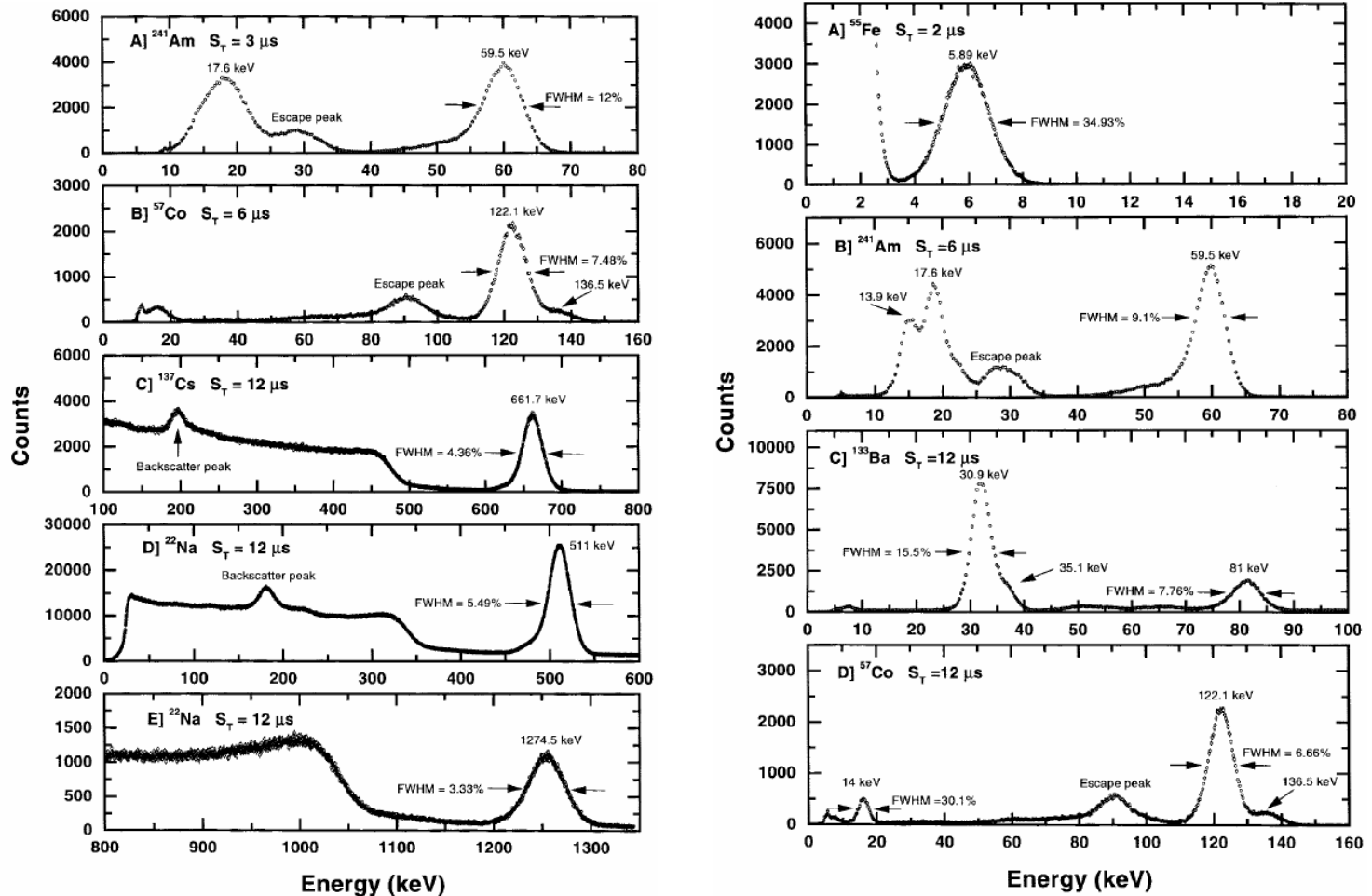


- CsI(Tl), 3mm
 $\eta = 80 \% (122 \text{ keV})$
- gain
 15.4 el./keV
- position resolution
 0.35 mm FWHM
- energy resolution
 $17.4 \% \text{ FWHM}$
 $E(\text{min}) = 2 \text{ keV}$

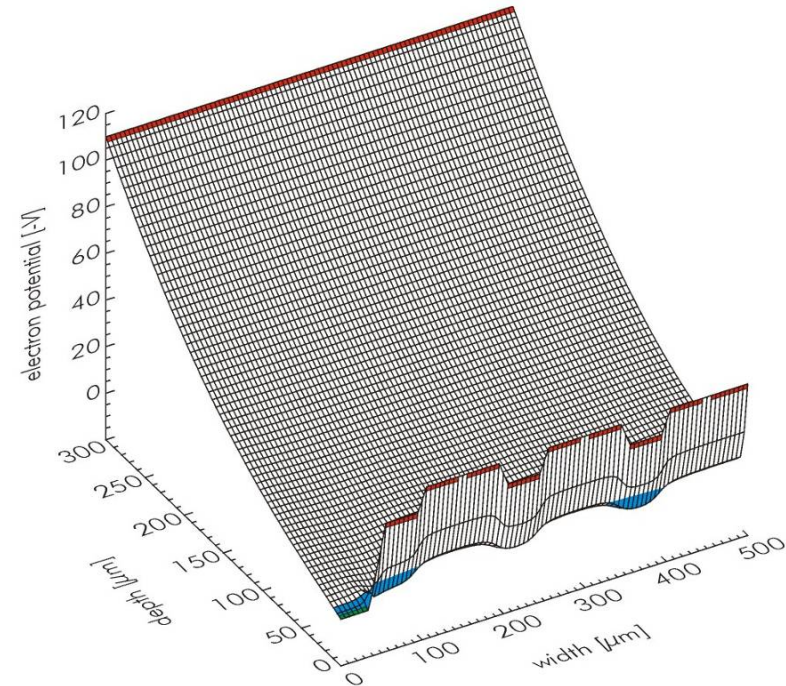
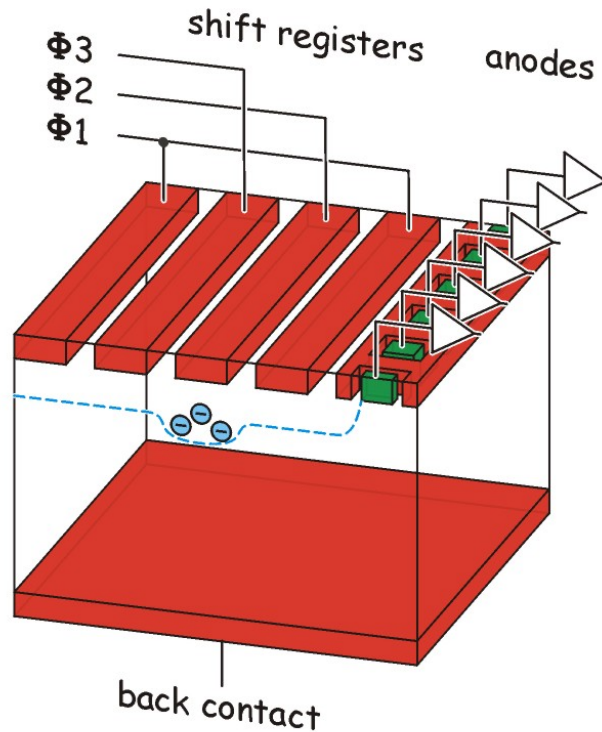


experiment & figures by C. Fiorini,
Politecnico di Milano

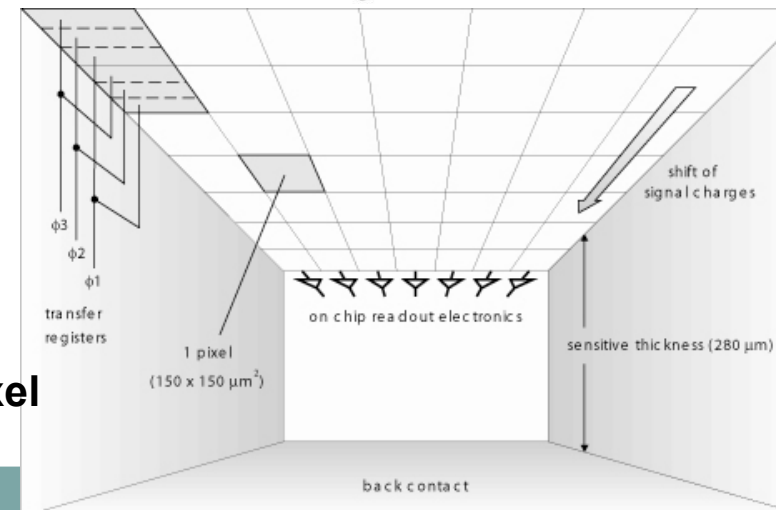
Measurements by C. Fiorini, A. Longoni, Politecnico di Milano



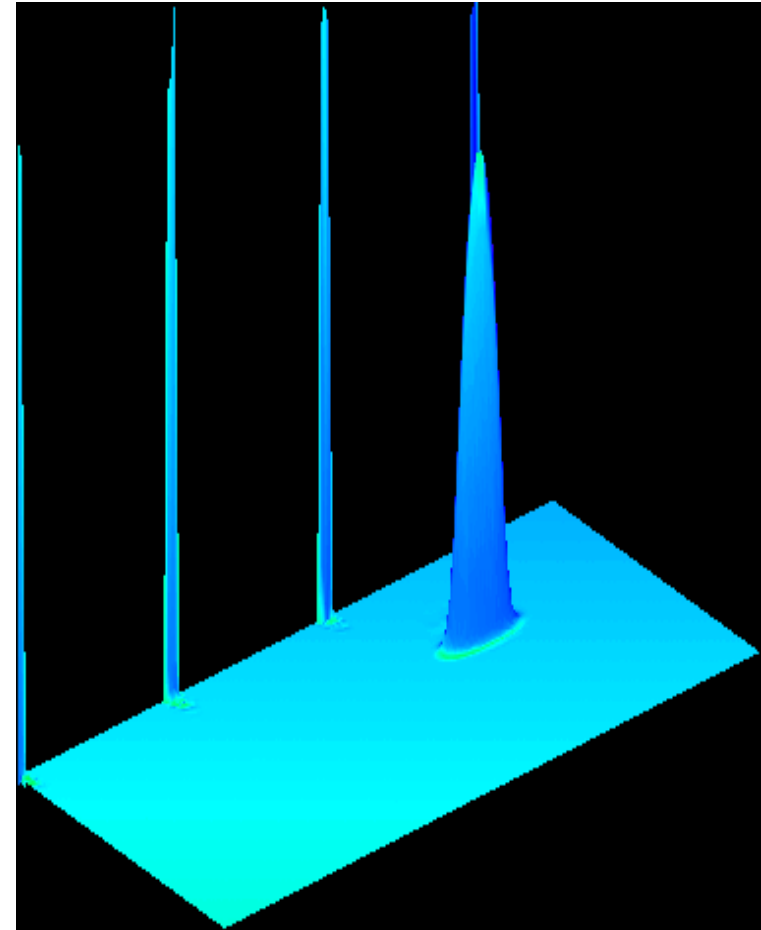
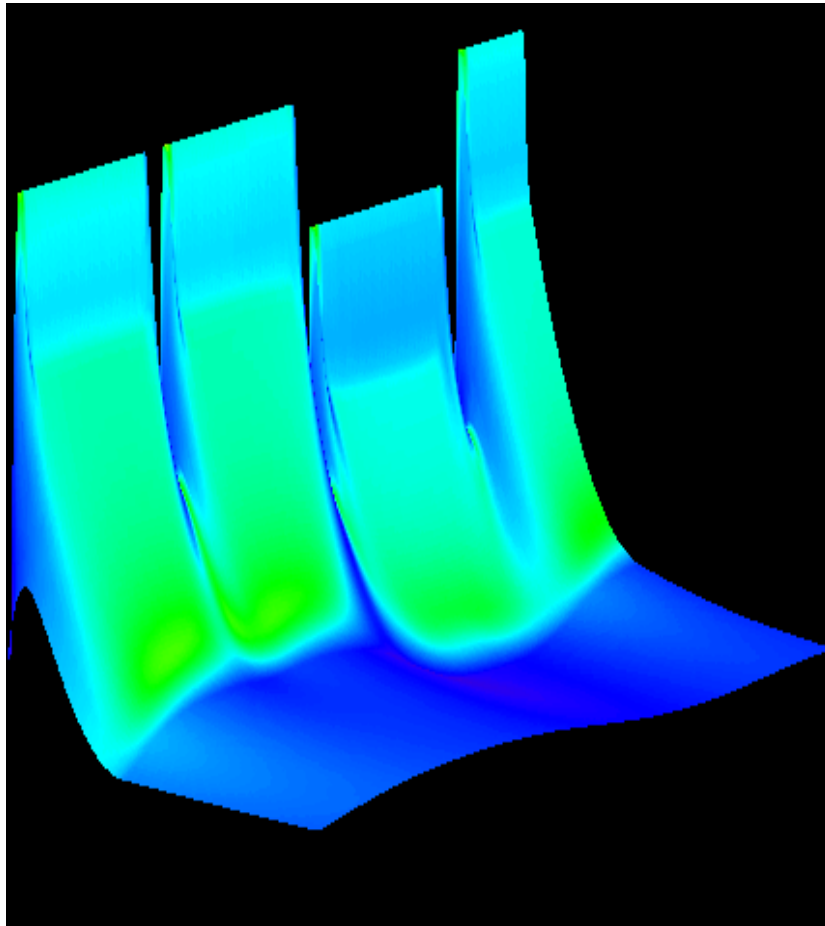
From SDDs to CCDs

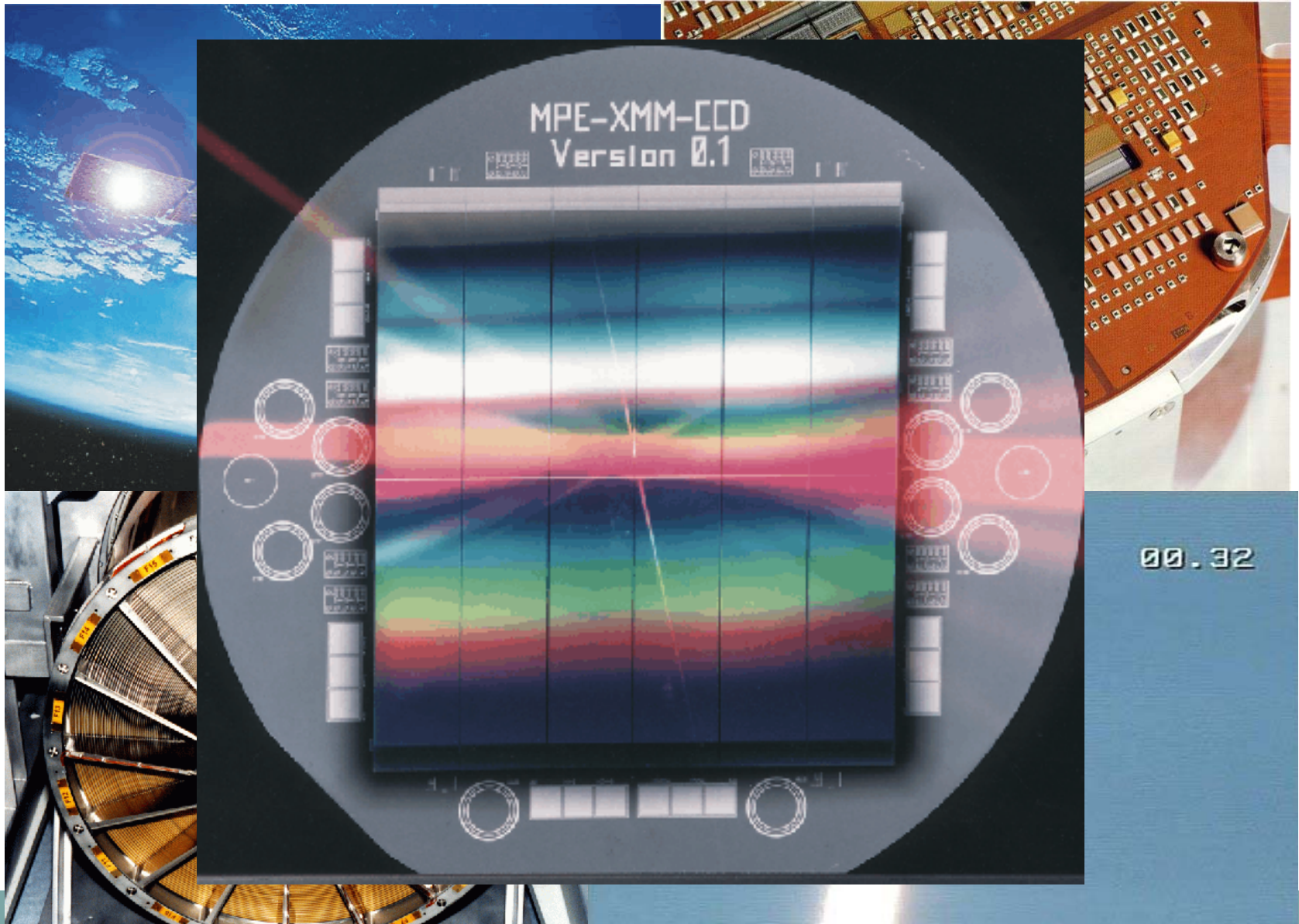


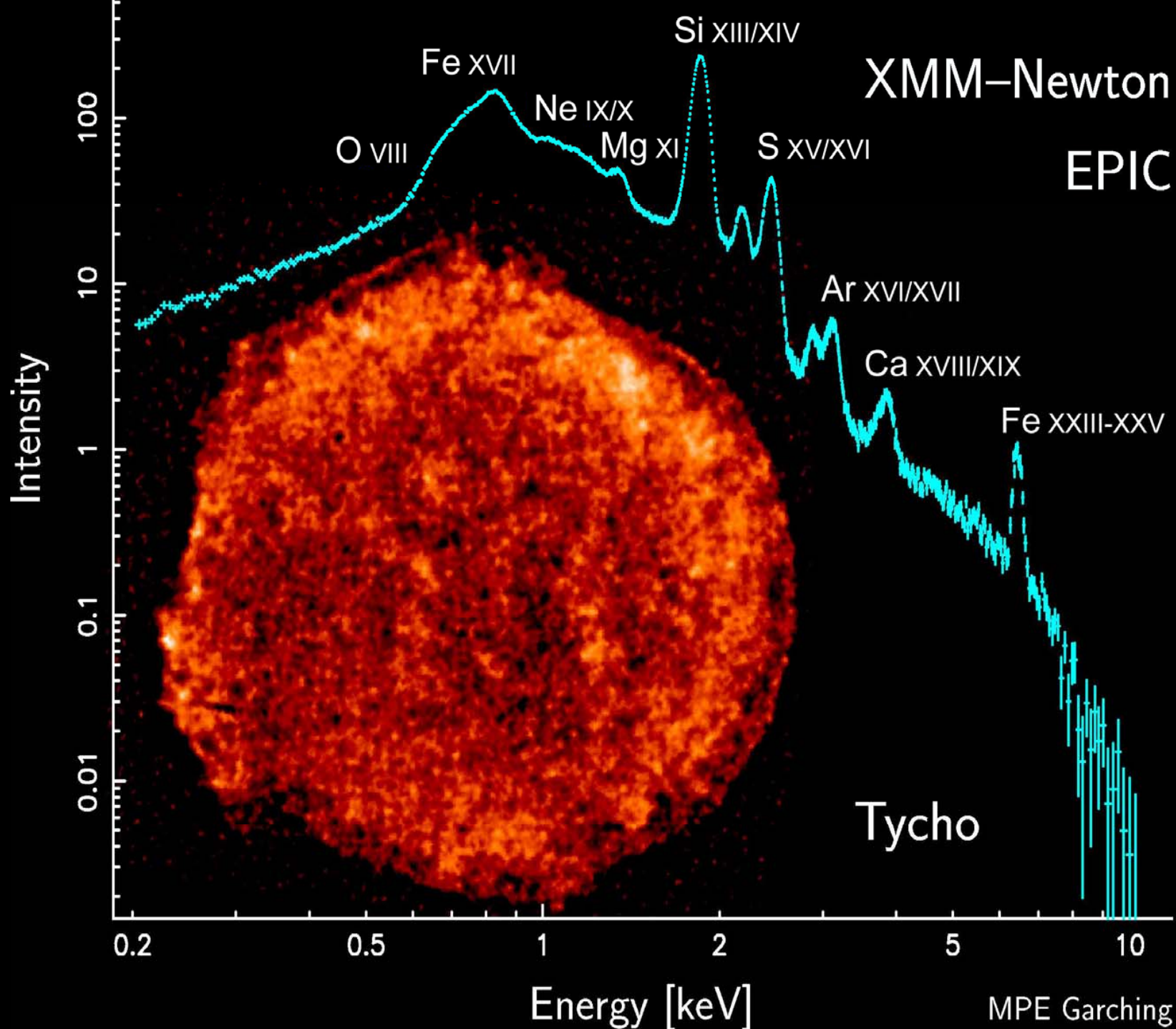
- full depletion (50 μm to 500 μm)
- back side illumination
- radiation hardness
- high readout speed
- pixel sizes from 30 μm to 1 mm
- charge handling: more than 10^6 e⁻/pixel
- high quantum efficiency



Charge transfer in the pnCCD





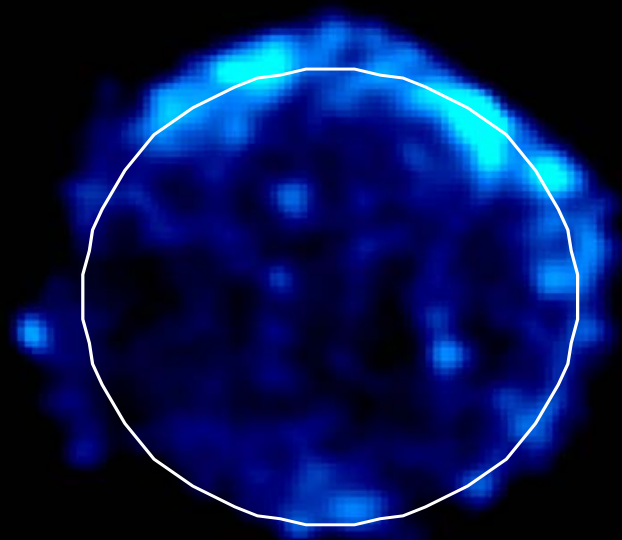
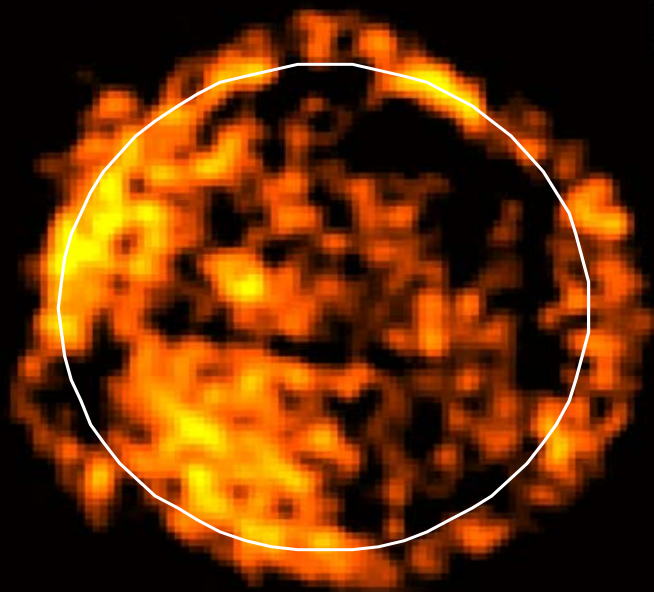


Magnesium

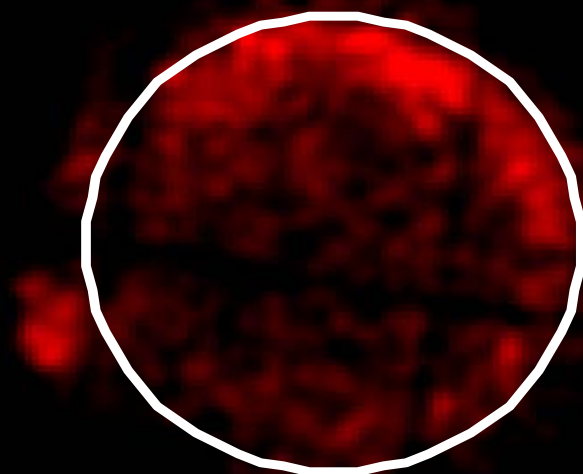
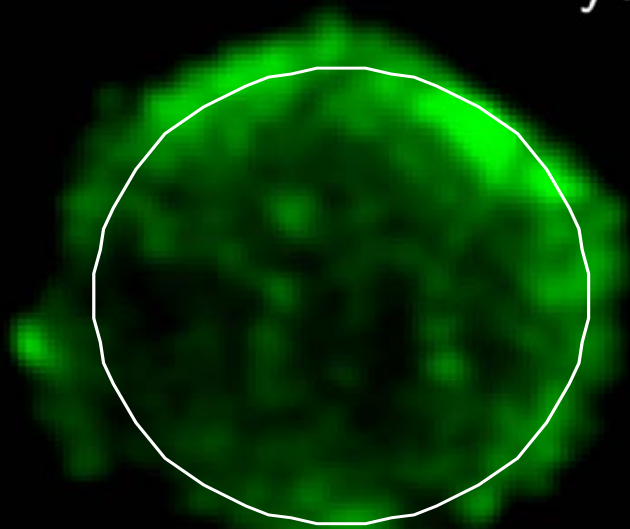
XMM-Newton

Silizium

EPIC



Tycho's SNR



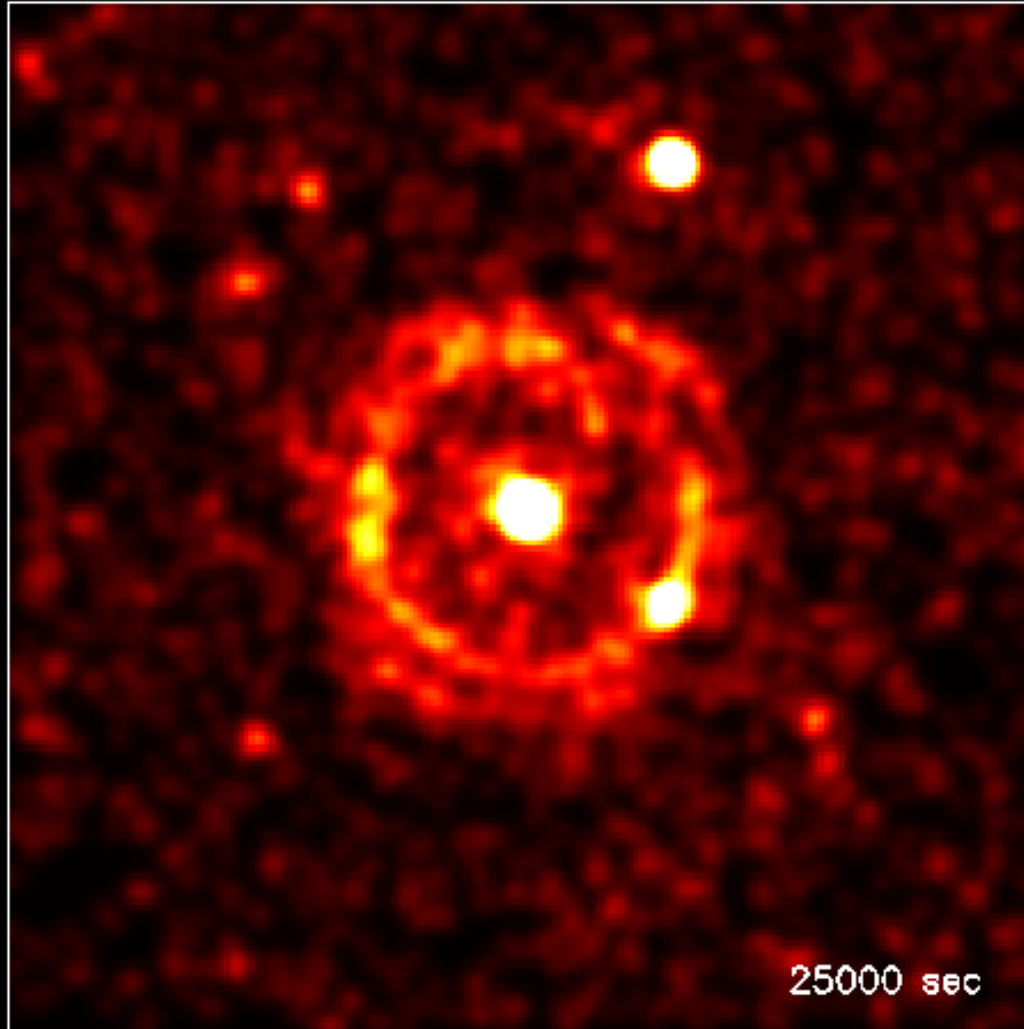
Schwefel

Eisen

Gamma ray burst afterglow observation with XMM



GRB 031203 XMM-Newton observation

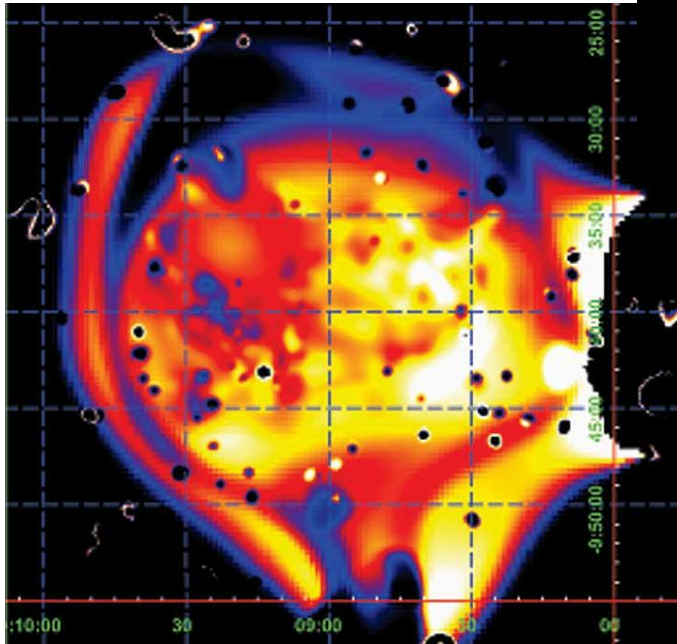
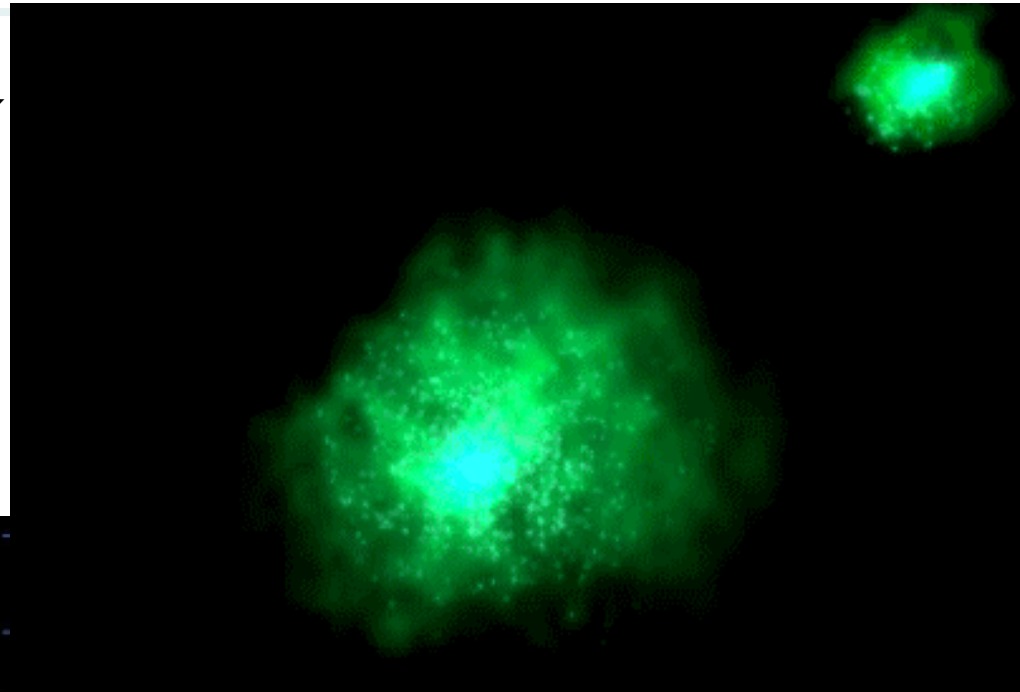


ESA, S. Vaughan (University of Leicester)

Head-on collision of clusters of galaxies observed with XMM

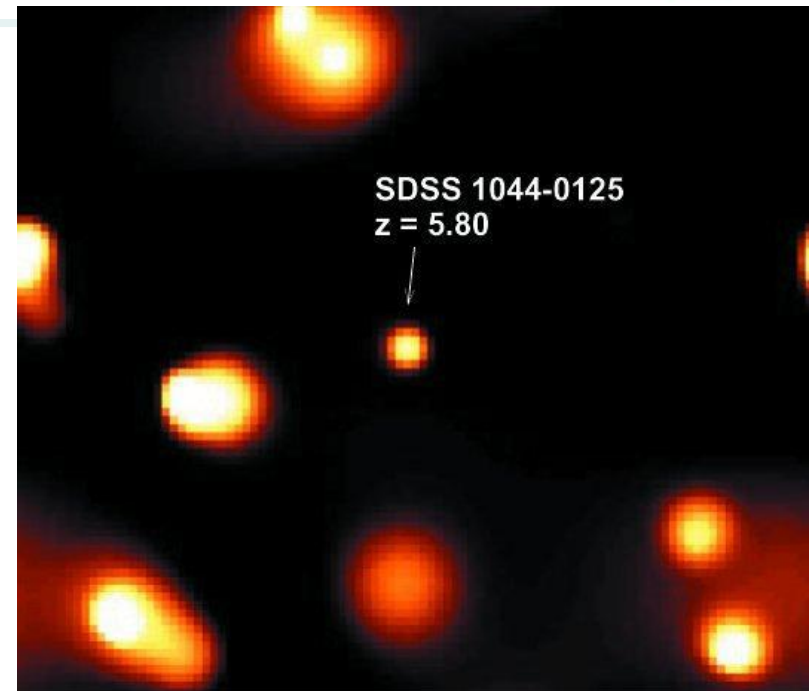


model of the ``cosmic
thunderstorm``

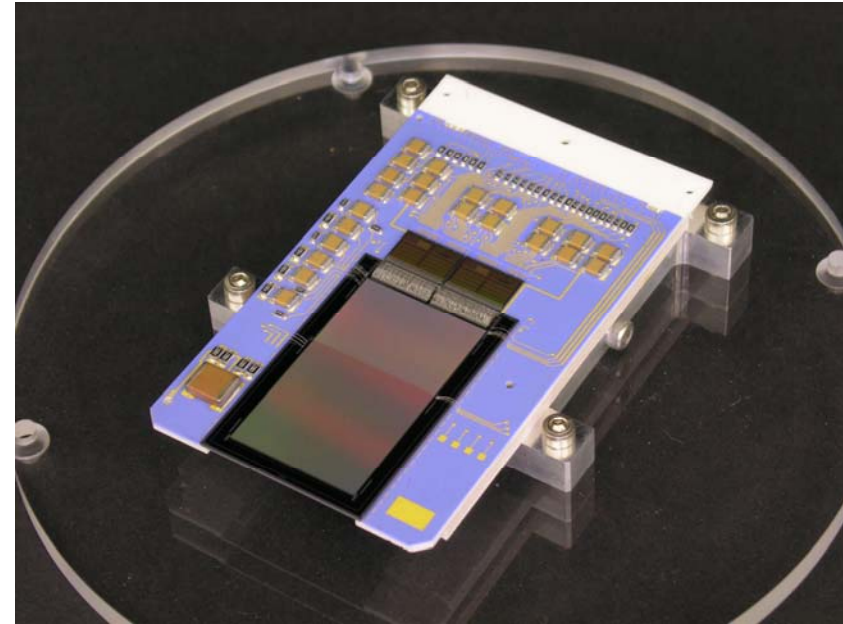
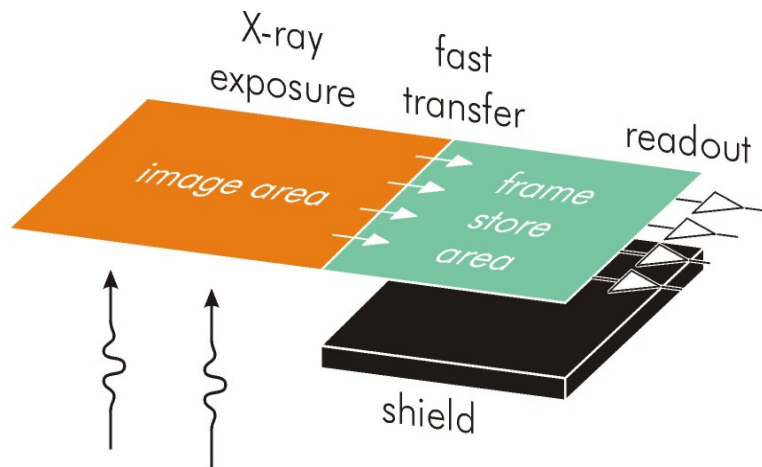


measured temperature and density maps from
XMM – Newton of Abell 754

1. Working since launch (10. Dez. 1999) without any problem.
2. The energy resolution @ the Al_K line (1.5keV) decreased since launch from 98 eV to 99 eV (FWHM).
3. Since launch the operating conditions have never been changed.
4. Up to now about 6000 observations were made with XMM - Newton. In 80 % of all observations the pnCCD was chosen as 'prime instrument'.
5. Up to now, 900 refereed astrophysics papers have been published



QSO SDSS 1044-0125



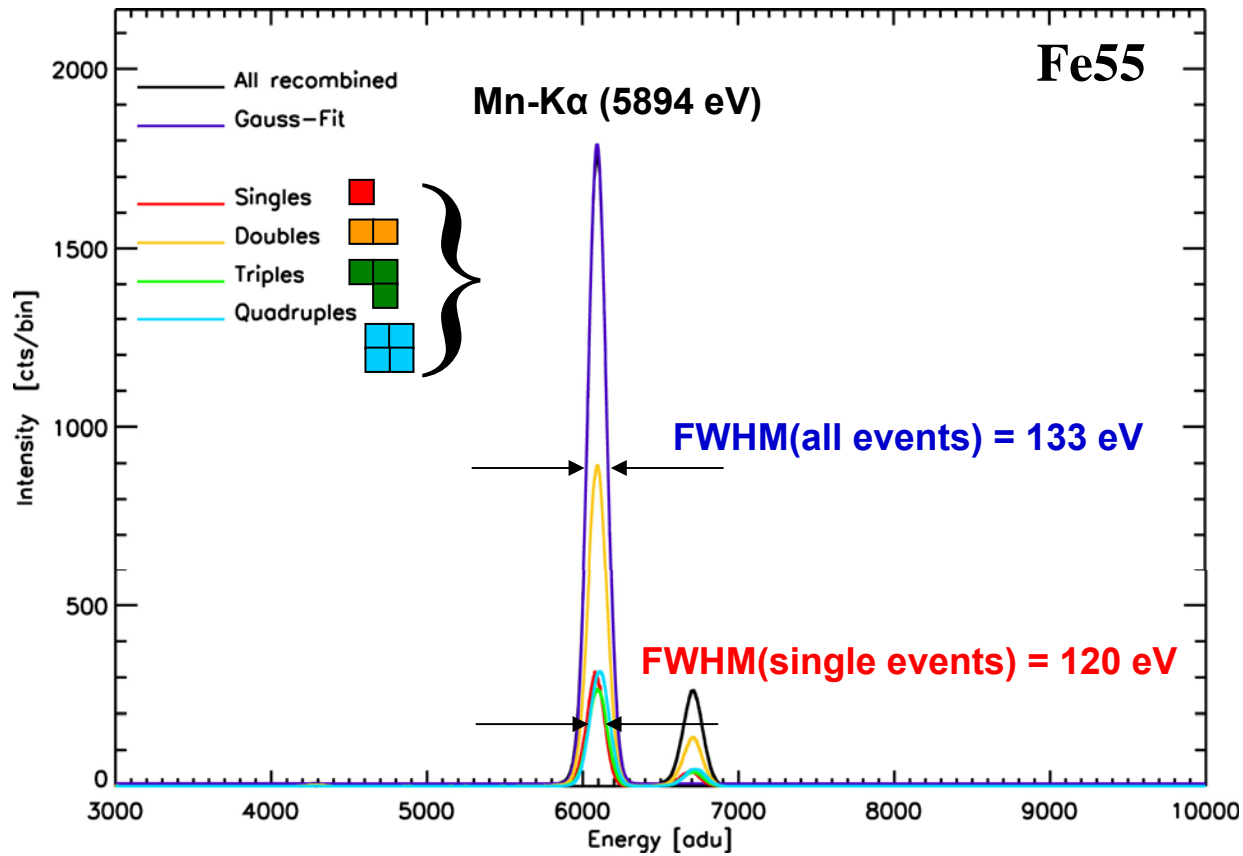
FS pn-CCD for the ROSITA mission (ESA, DLR, RSA)

- format 256 x 256
- pixel size 75 μm \square image
 50 μm \square frame store
- out-of-time 0.1 %

III. Performance: spectroscopy Fe55



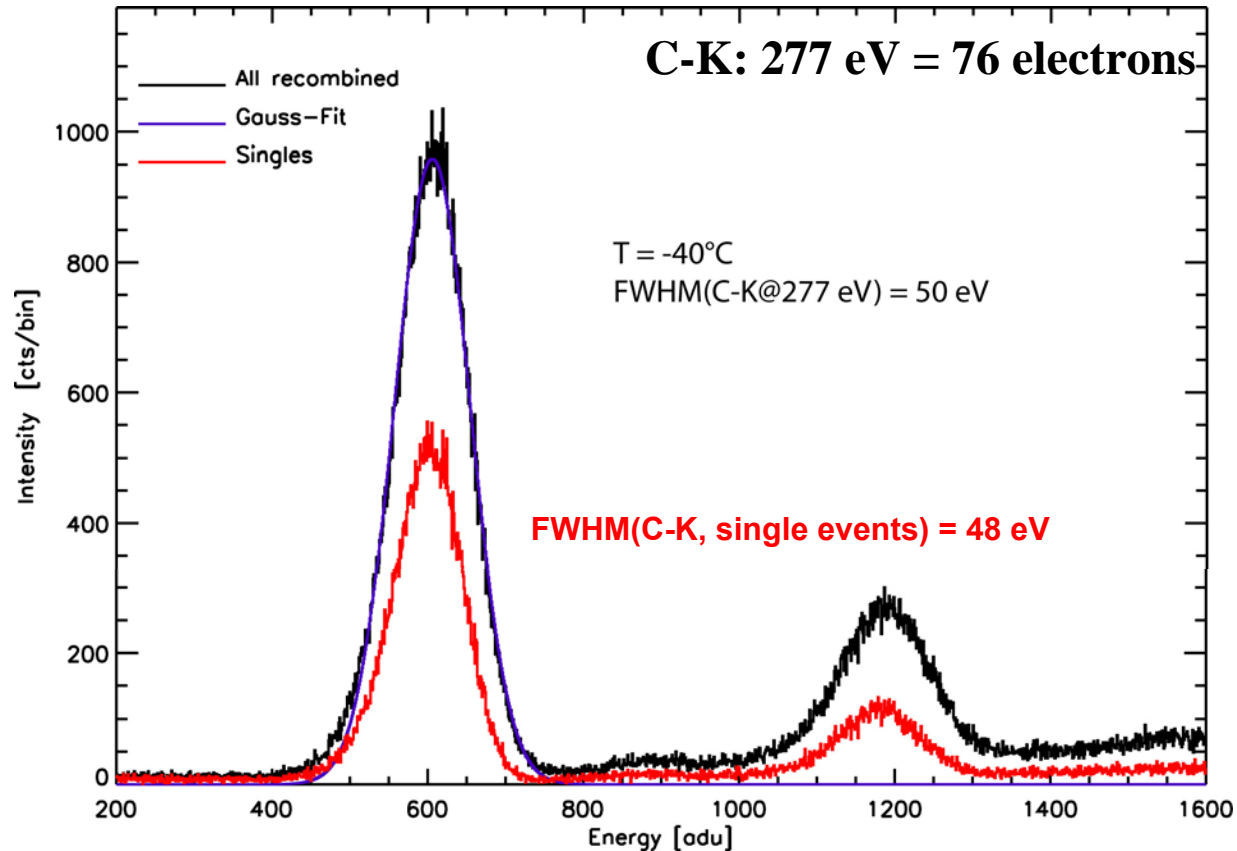
C11_11_61_050422_01, T = -83°C; 54 ms



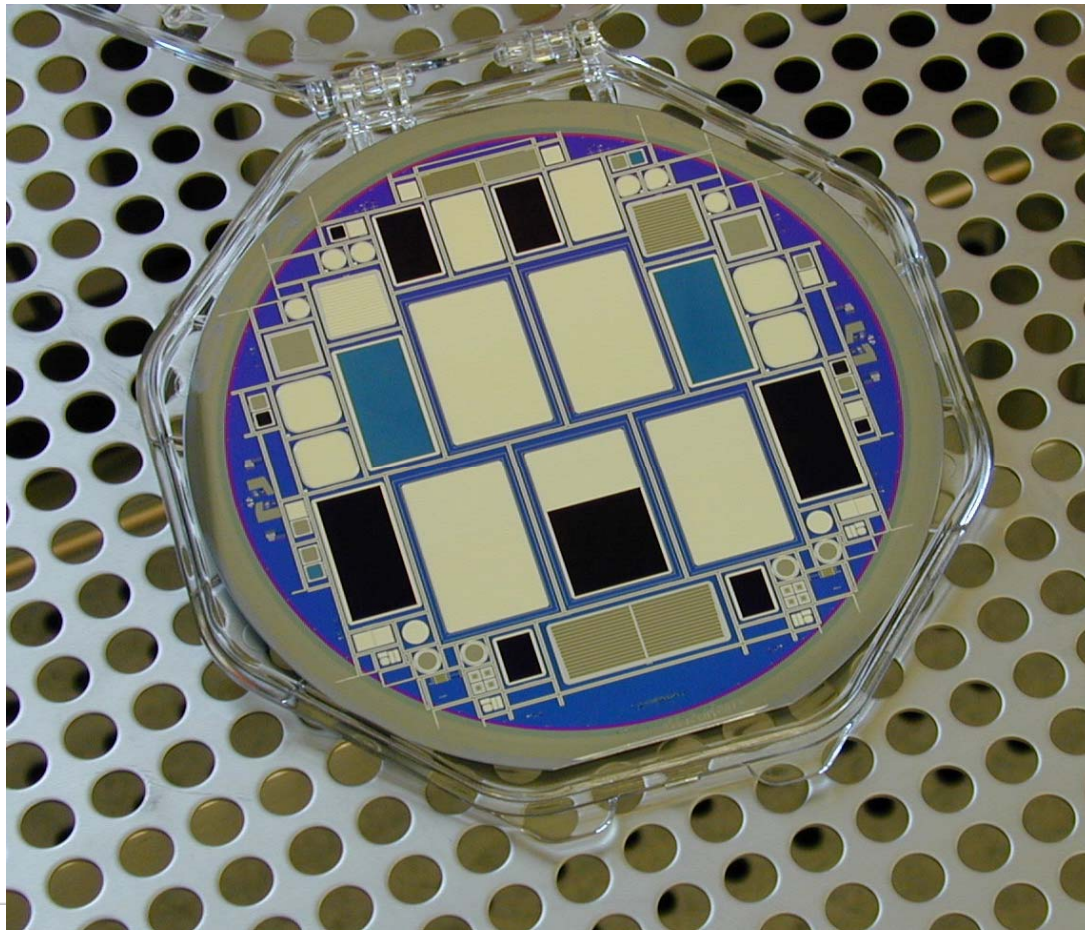
III. Performance: spectroscopy 277 eV



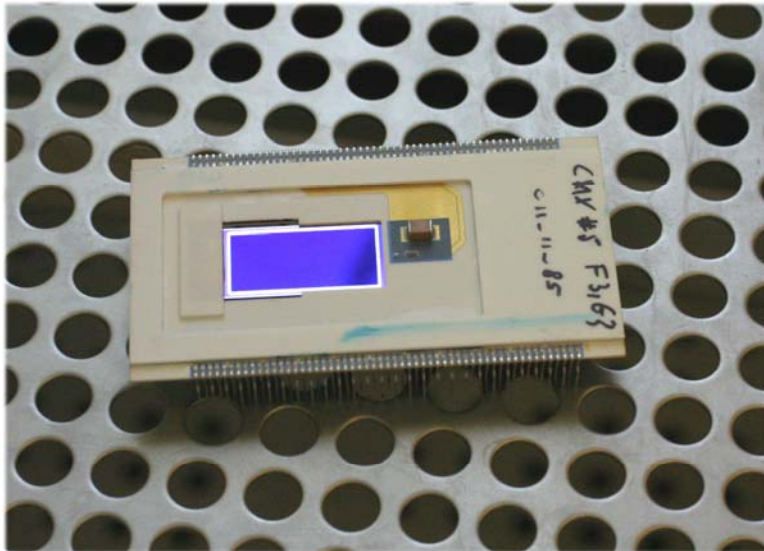
C11_11_25_050512_02



150 mm wafer of recent CCD fabrication

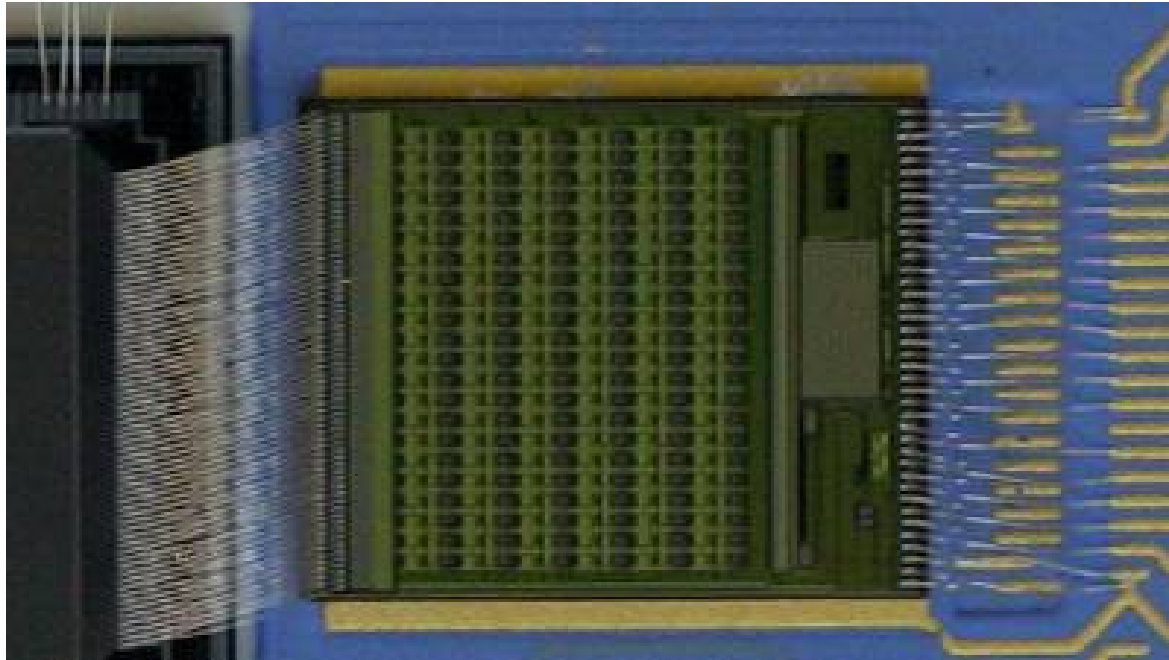


51mm pnCCD with a double-sided readout, mounted onto a ceramic substrate



- detector size = $27 \times 13.5 \text{ mm}^2$
- $51 \text{ }\mu\text{m}$ \square pixel size
- 528×264 pixel in total,
132 \times 264 in each image & storage area
- readout transfer to both sides
- image transfer time = $30 \text{ }\mu\text{s}$
- OOT probability = 3% @ 1000 fps
- charge transfer loss CTI $\approx 10^{-5}$
i.e. total charge loss < 0.15 %
- charge handling capability $> 10^5 \text{ e}^-$
- 100% fill factor
- readout noise vs. frame rate:
 - 1.8 e^- @ 10 .. 400 fps
 - 2.3 e^- @ 400 .. 1.100 fps
- With binning:
 - 2.3 e^- @ 2.200 .. 4.400 fps

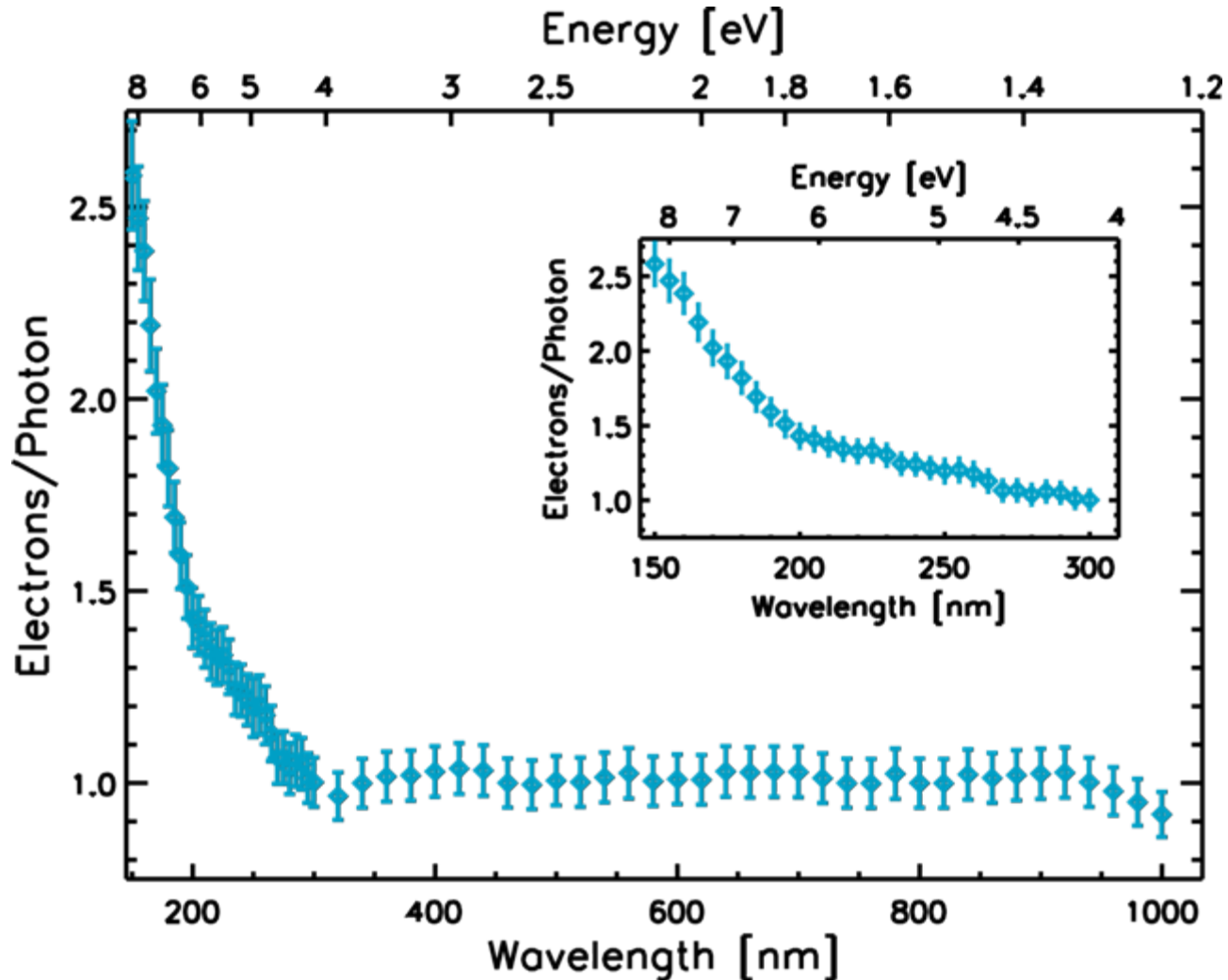
CAMEX amplification- and readout-chip



- Multi-correlated double-sampling filtering (MCDS)
- Signal processing of all channels in parallel (132)
- Selectable gains and operating modes
- Electronic noise contribution less than $1 e^-$
- Readout-speed per node up to 10MHz (i.e. $6.6\mu s$ per line on two readout nodes)

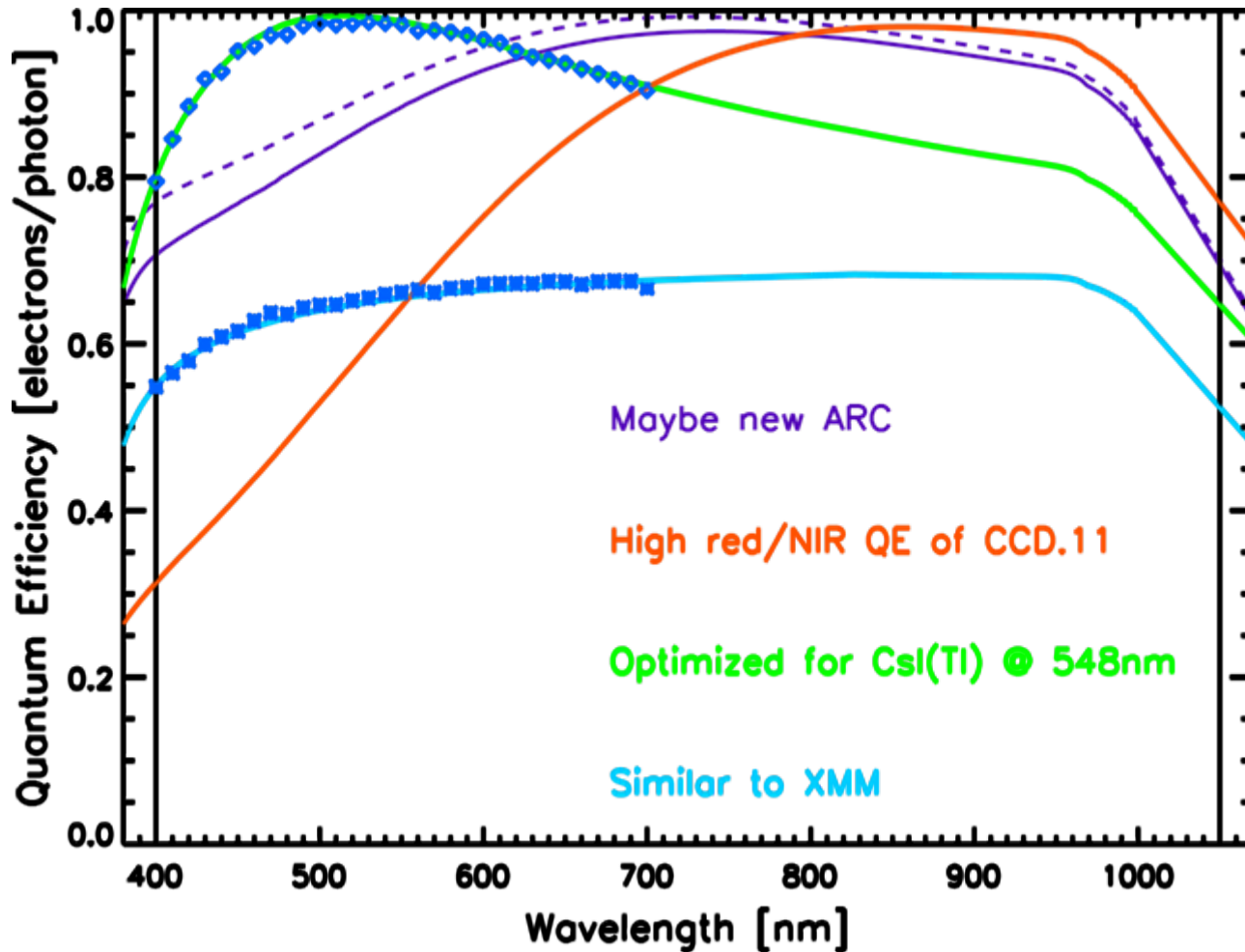


Internal quantum efficiency

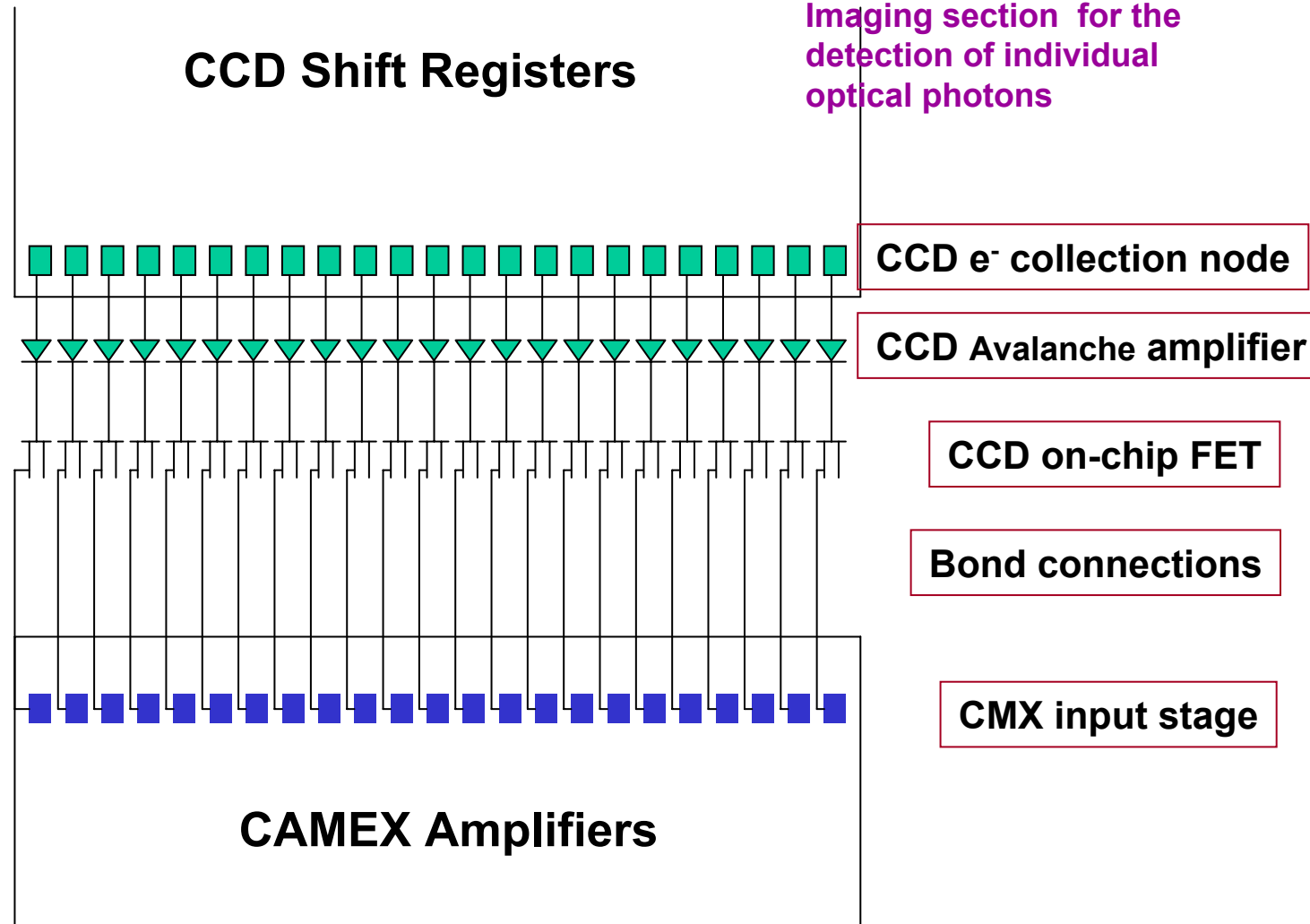




Measurement and calculations of optical response



Fast pnCCDs for single photon counting in the optical

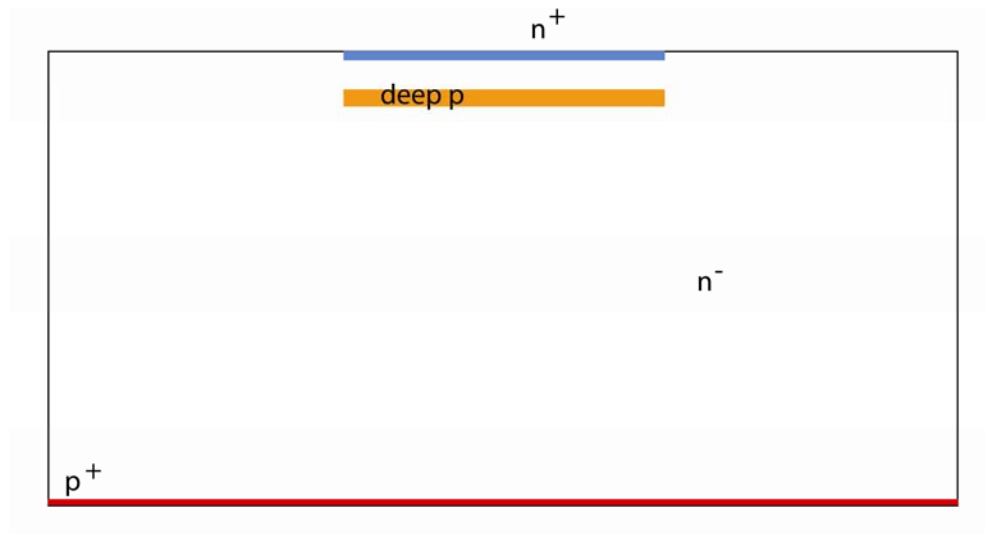




- ◆ **Basic idea:**
 - Move radiation entrance to backside of fully depleted device
 - Focus signal electrons on (small) avalanche region
- ◆ Development of concept to be shown in several steps



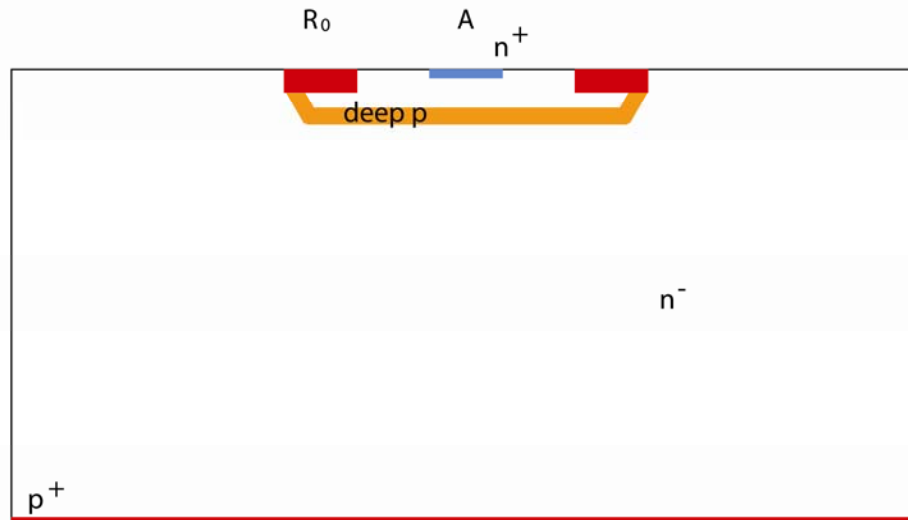
- ◆ Fully depleted bulk radiation entrance on backside
 - Adjustment of field needs large voltage variation



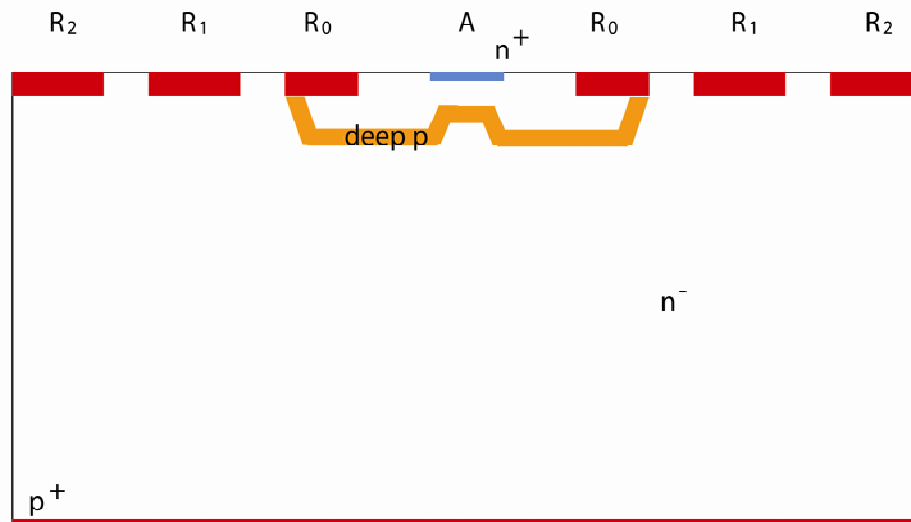
Development of concept II



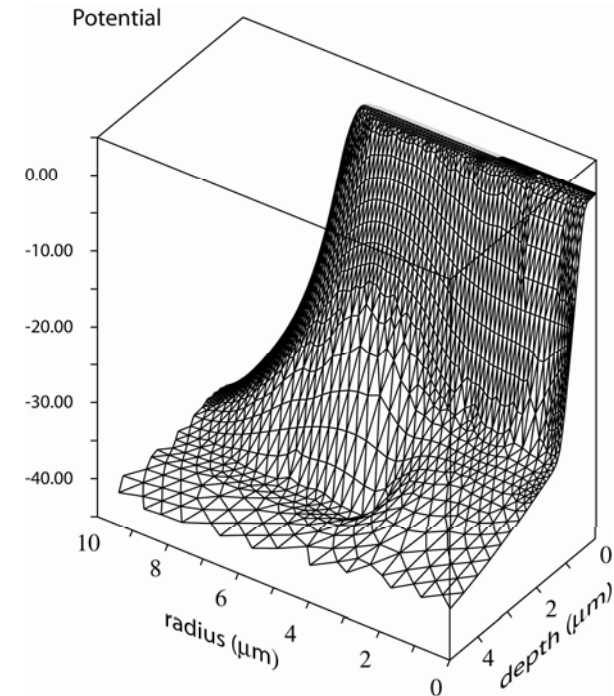
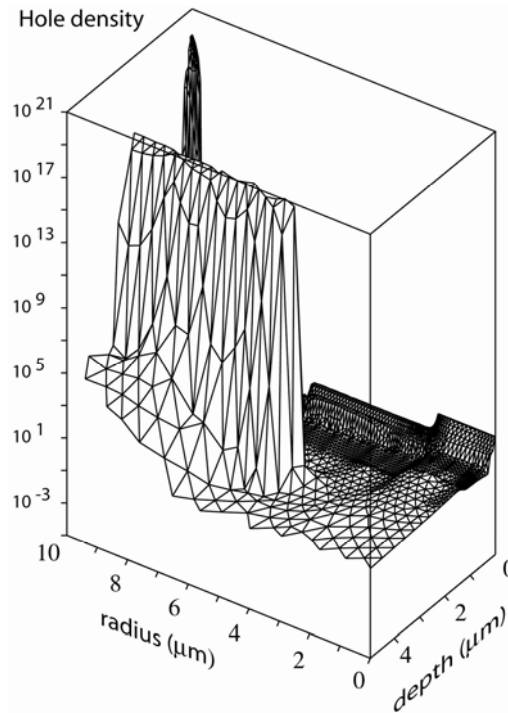
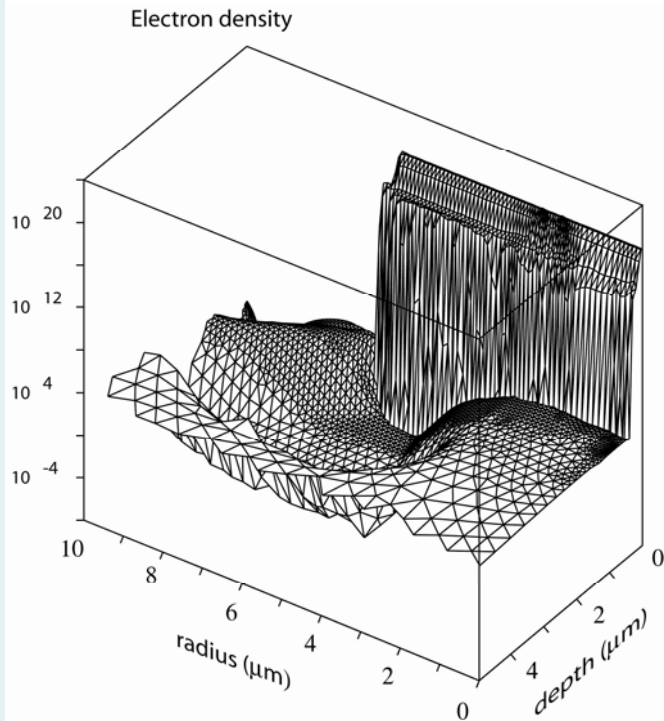
- ◆ Fully depleted bulk radiation entrance on backside
- ◆ Biasing from top ring-like structure
 - Gives better control of high field region



- ◆ Fully depleted bulk radiation entrance on backside
- ◆ Biasing from top ring-like structure
 - Modulation of depth of buried p-layer
 - Addition of drift rings
 - Focusses electrons to centre

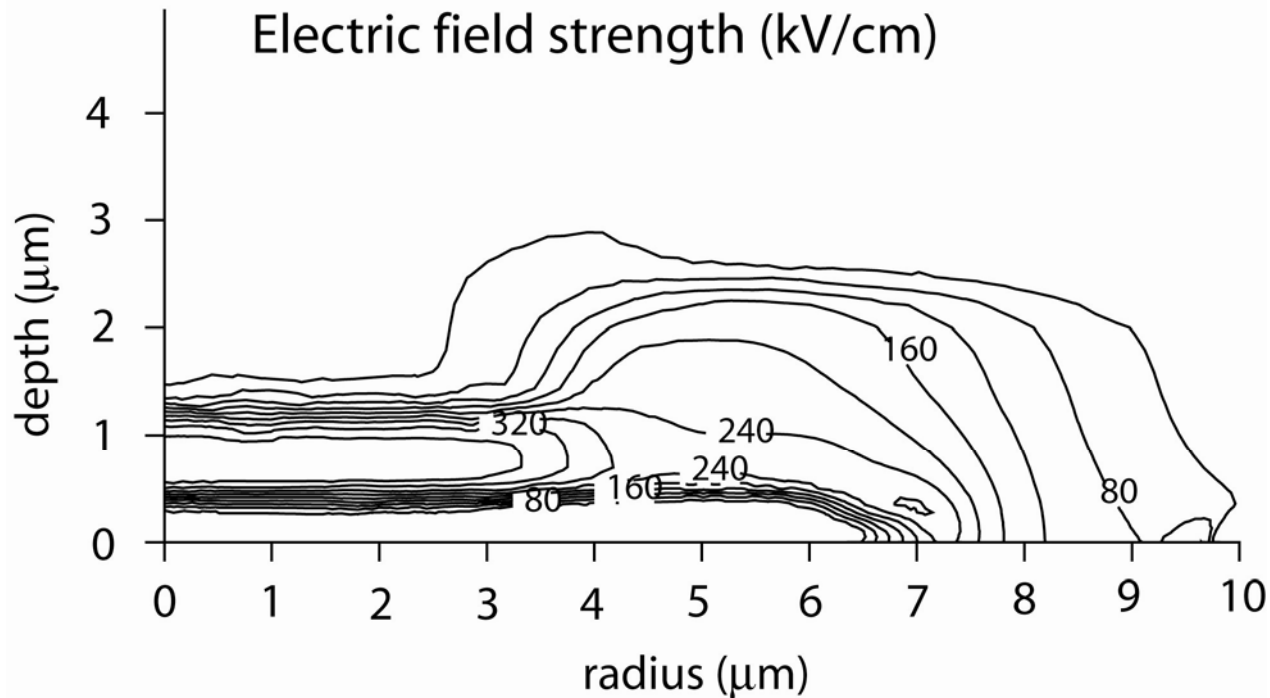


◆ Electron and hole distribution around avalanche region

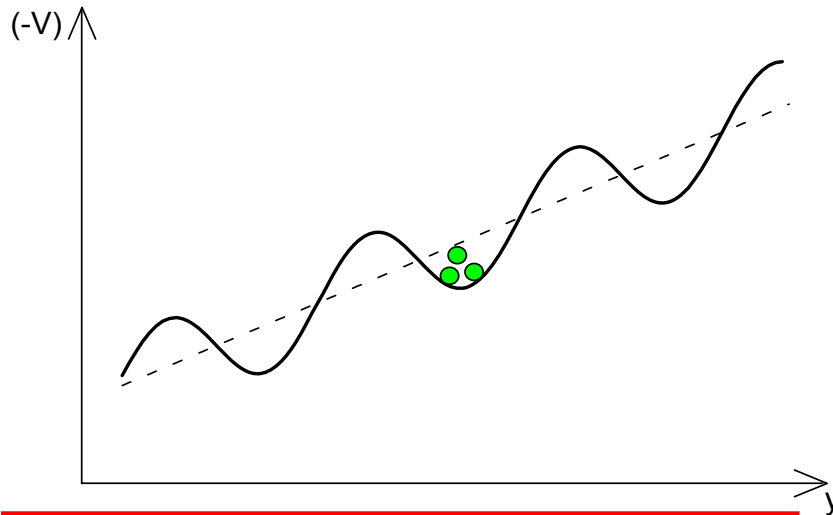




- ◆ **Electric field distribution in avalanche region**
 - **Uniform field distribution up to 3 μm radius**
 - **All signal electrons enter avalanche region at smaller radius**

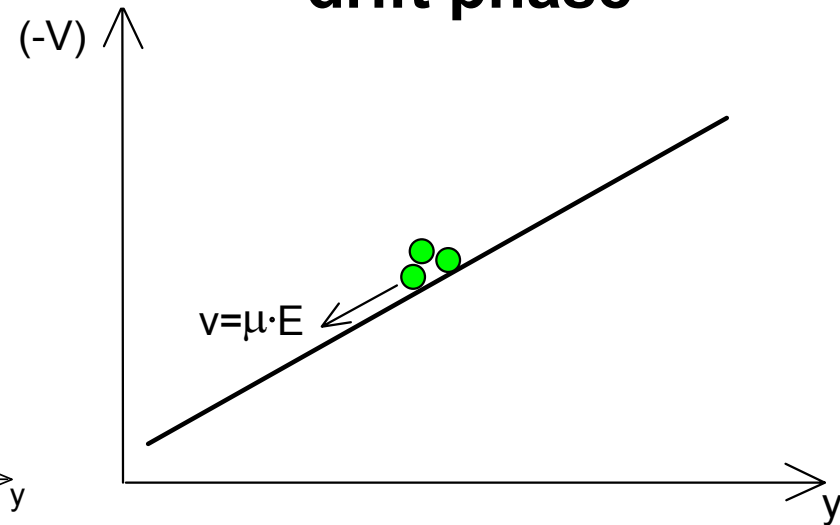


integration phase



- **suitable perturbation**
superposed to the linear bias
blocks the drift.
- **integration wells**
fully confine the signal electrons.

drift phase



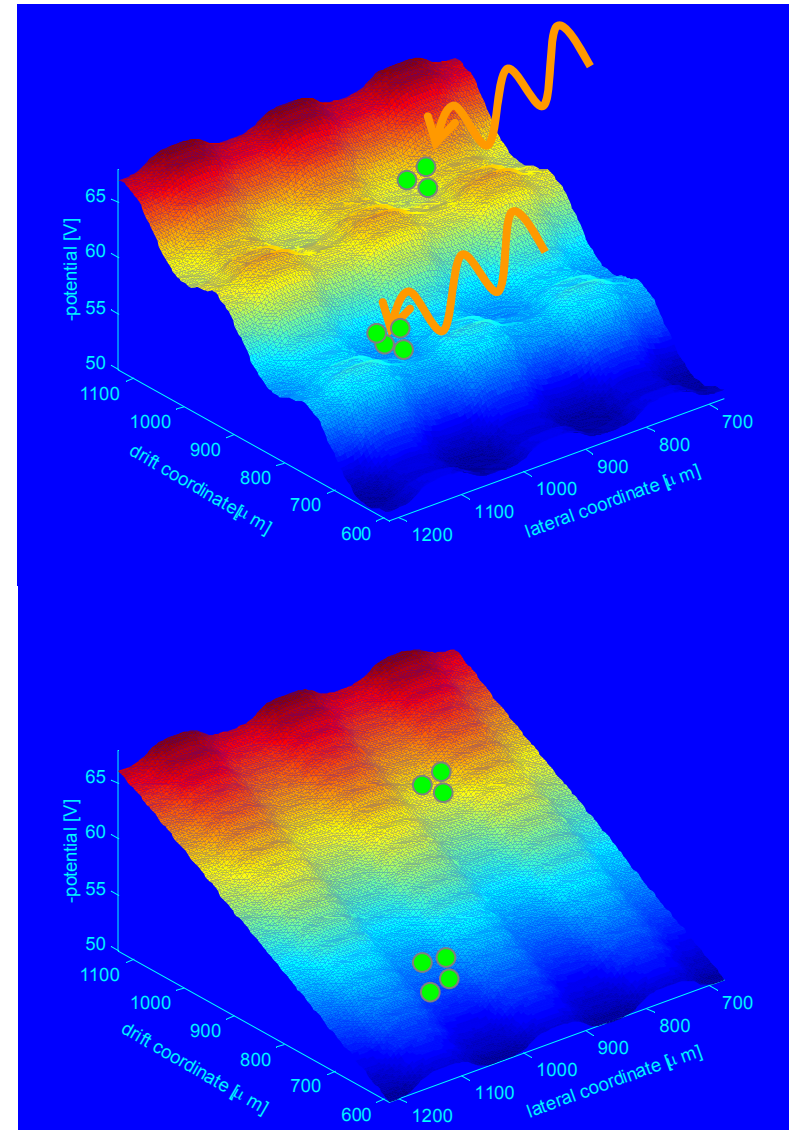
- the **barriers** that block the drift are **removed.**
- a **static field drifts** the signal electrons to the anodes.



1. The Compton Camera Concept
2. The Controlled Drift Detector (CDD)
3. First Tests
4. Fast Timing

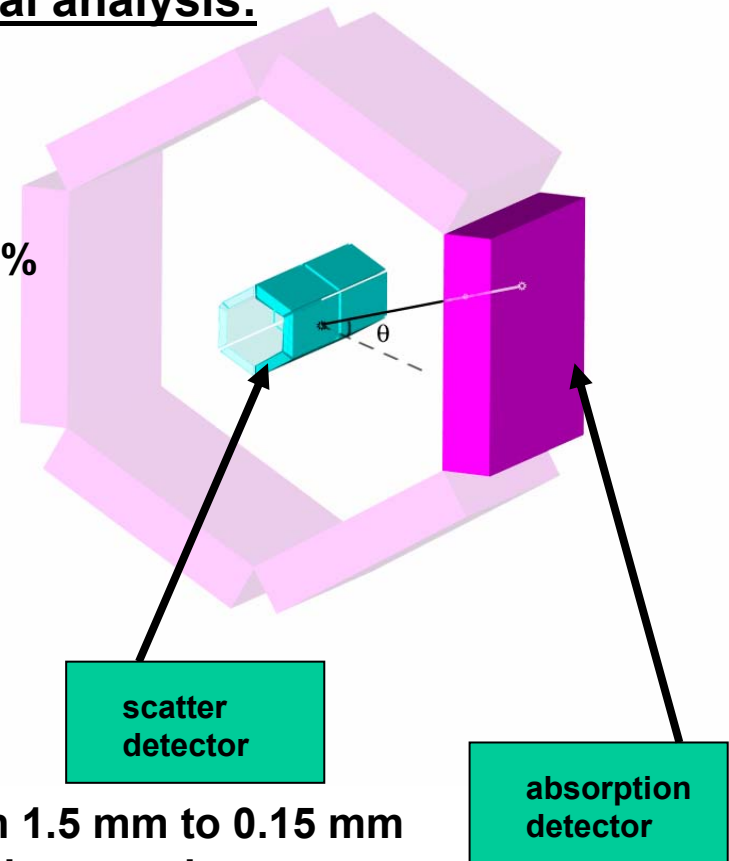
Participating Institutions:

1. Universität Siegen (D)
2. Politecnico di Milano (I)
3. MPE-HLL (D)
4. Universität Bonn (D)
5. Universität Essen (D)
6. Vanderbilt University (USA)
7. University College London (UK)
8. University of Rome (I)
9. Universität Erlangen (D)
10. Forschungszentrum Jülich (D)



Advantages of CCI's for small animal analysis:

1. Position resolution can be as good as $100 \mu\text{m}$ ($\Delta\delta \approx 0.5^\circ$)
2. CCI is operated colimatorless
3. Total efficiency can be as high as 10 %
4. Performance gain with increasing X-ray energy
5. No inverse relation between resolution and sensitivity
6. Good intensity resolution



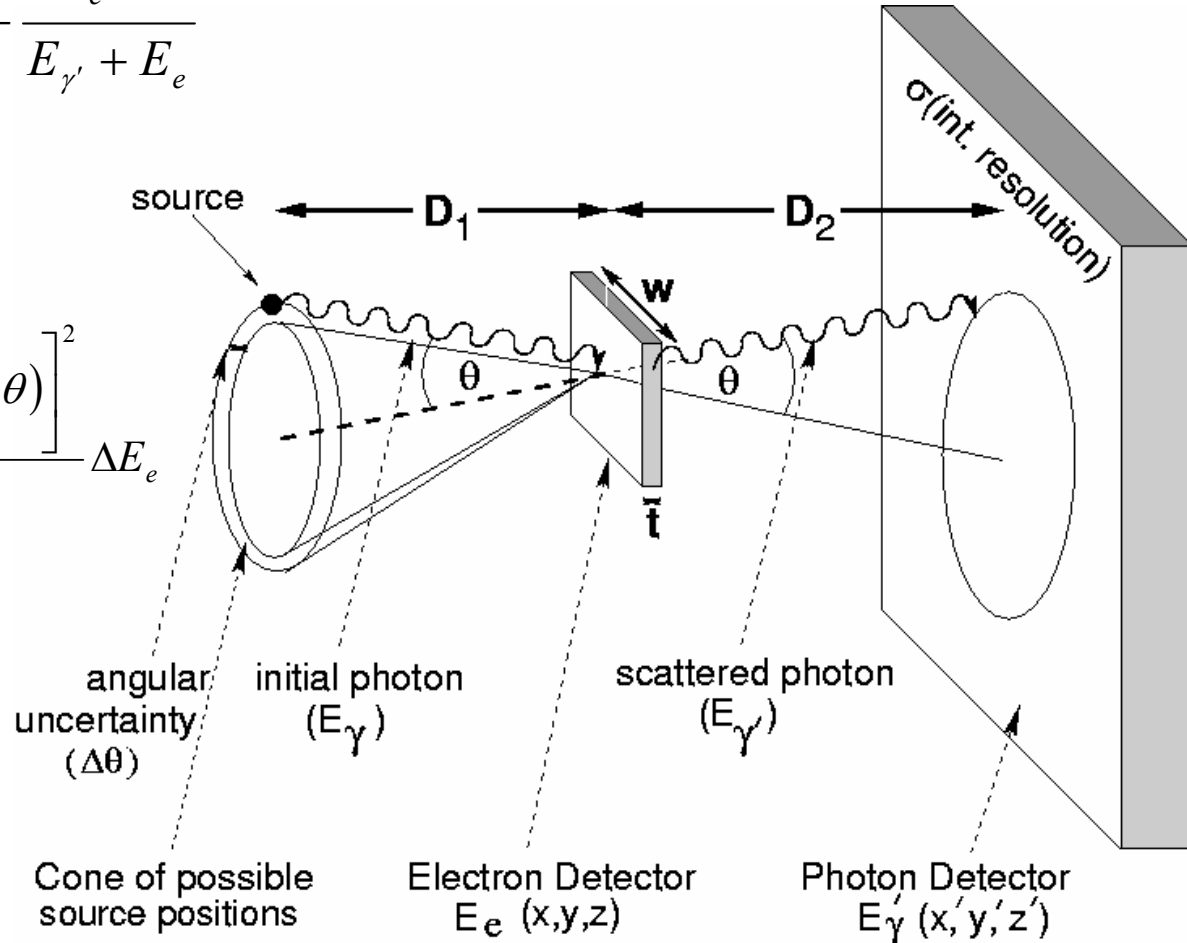
Our goals:

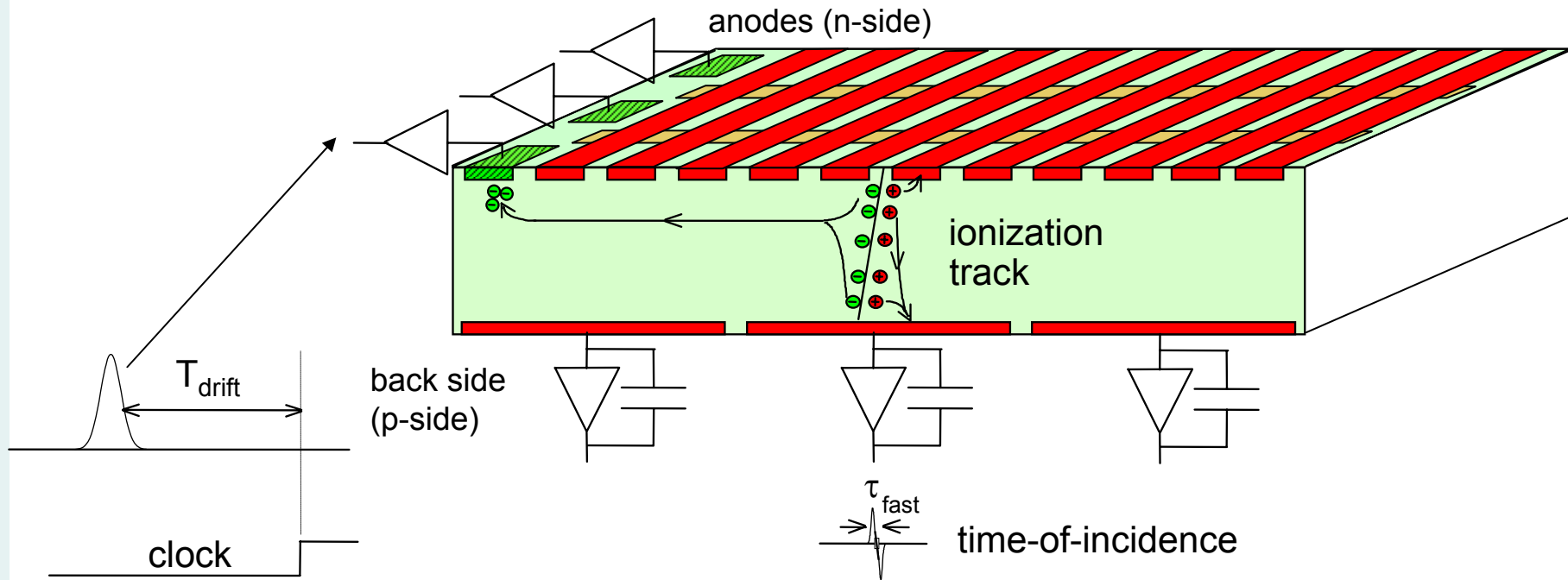
1. Improve in vivo image resolution from 1.5 mm to 0.15 mm
2. Determine the distribution of labeled drugs and genes with increased accuracy
3. Verify the targeting of receptor specific probes for clinical utility and drug development
4.



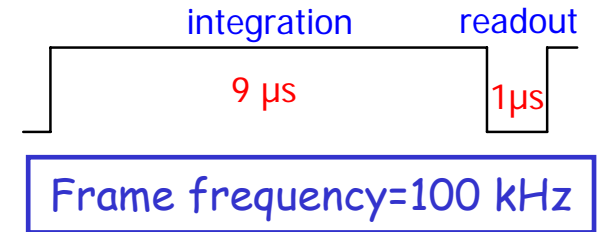
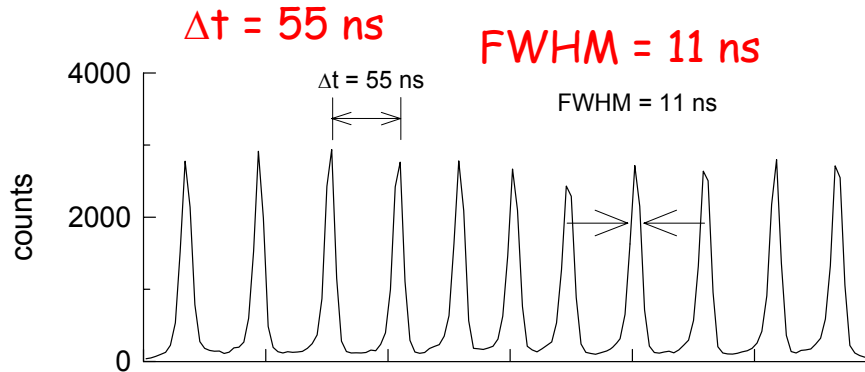
$$\cos \theta = 1 - \frac{m_e c^2}{E_{\gamma'}} + \frac{m_e c^2}{E_{\gamma} + E_e}$$

$$\Delta \theta_E = \frac{\left[1 + \frac{E_{\gamma}}{m_e c^2} (1 - \cos \theta) \right]^2}{\frac{E_{\gamma}^2}{m_e c^2} \sin \theta} \Delta E_e$$

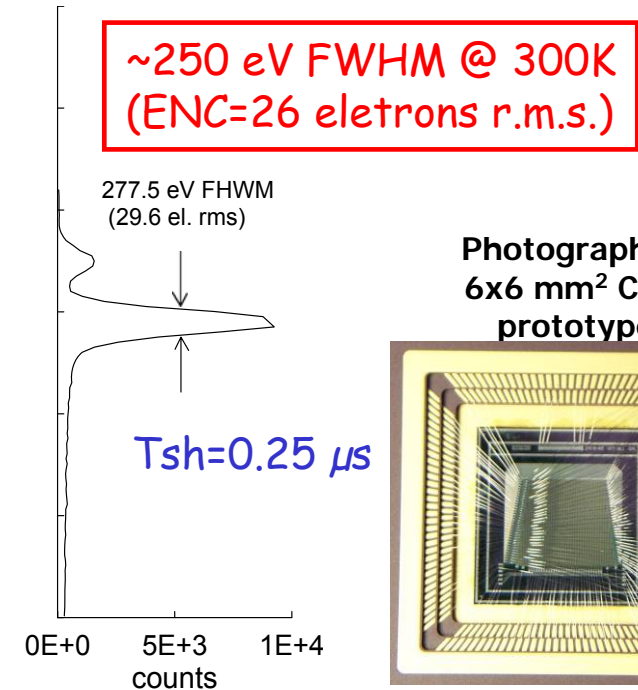
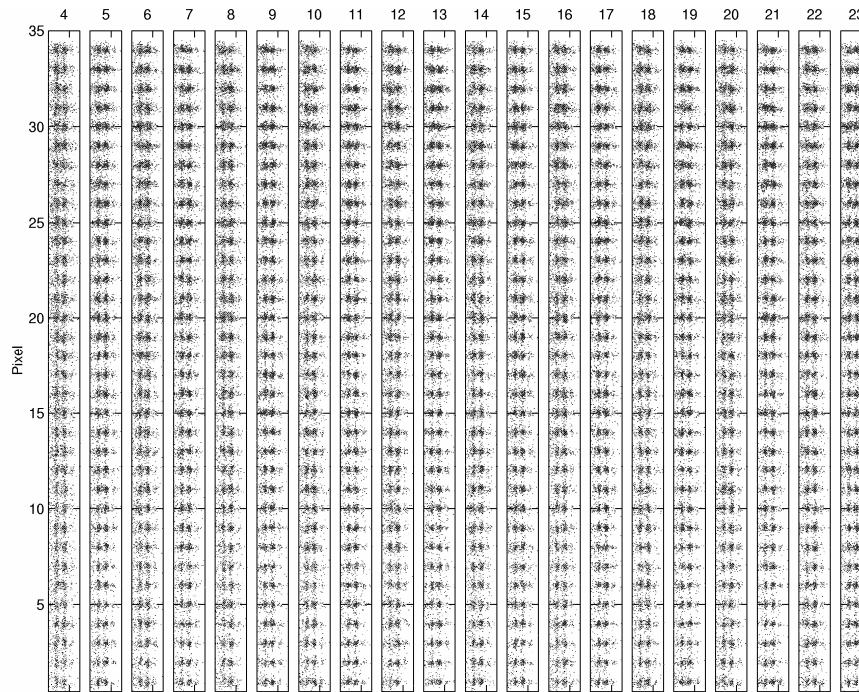




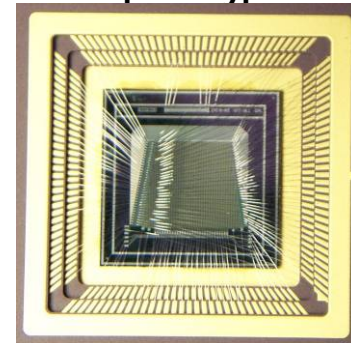
- fast trigger from electron-hole induction on back electrodes
- achievable time jitter depends on induction signals, electronic noise, etc..



Pixel $180\mu\text{m} \times 180\mu\text{m}$

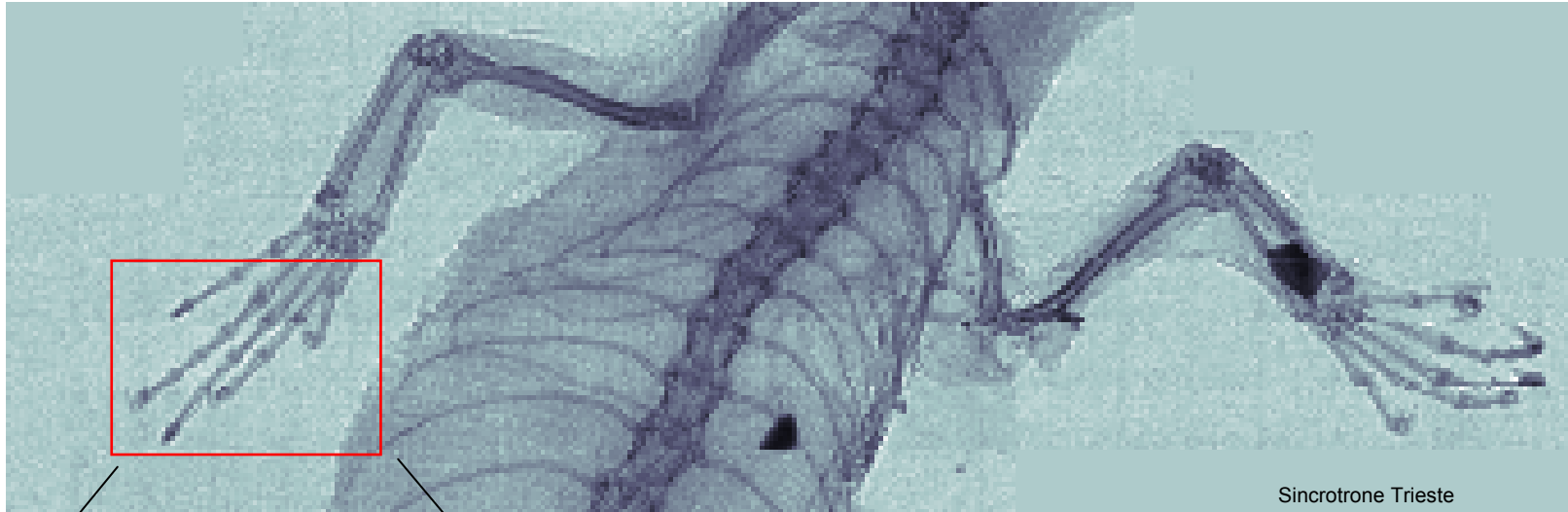


Photograph of 6x6 mm² CDD prototype

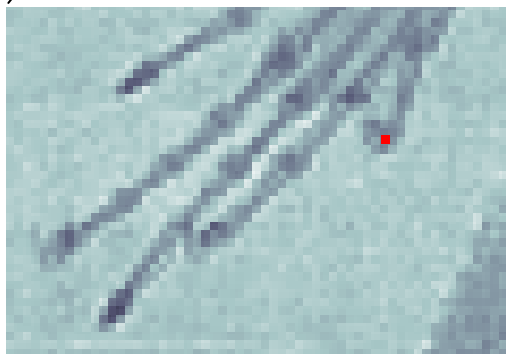


Radiographic image of a lizard...*

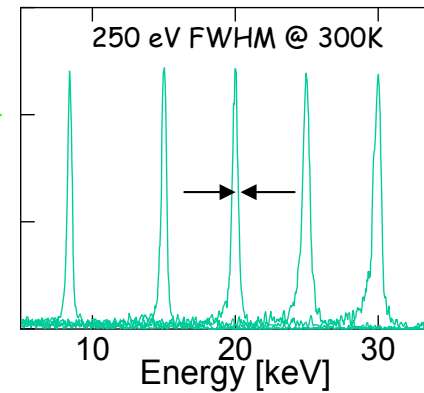
pixel size: 120 μ m, 10⁵ frames/s, T=300 K



* no animal was killed or has suffered for this measurement



...and spectroscopic analysis of each pixel

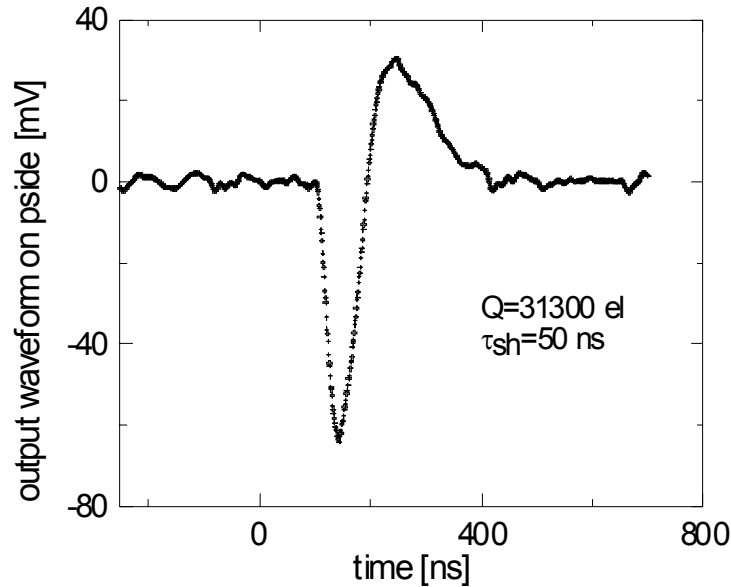


First experimental results

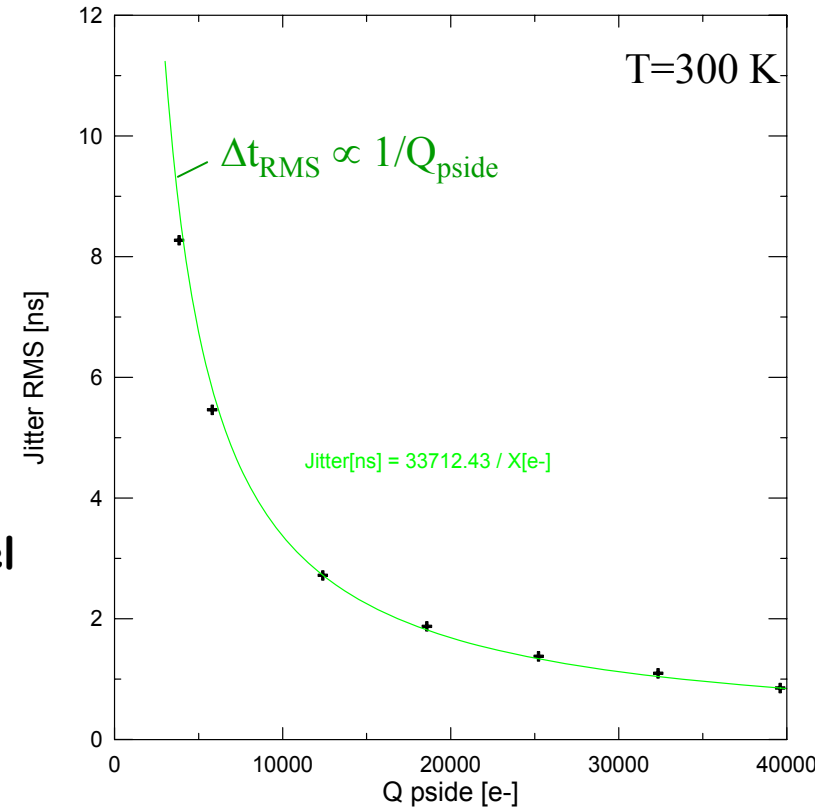
Pulsed IR 904 nm laser (pulse duration <100ps)



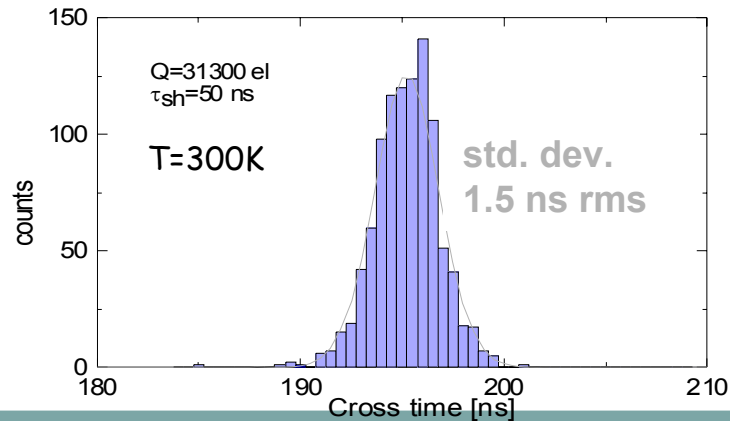
Output waveform

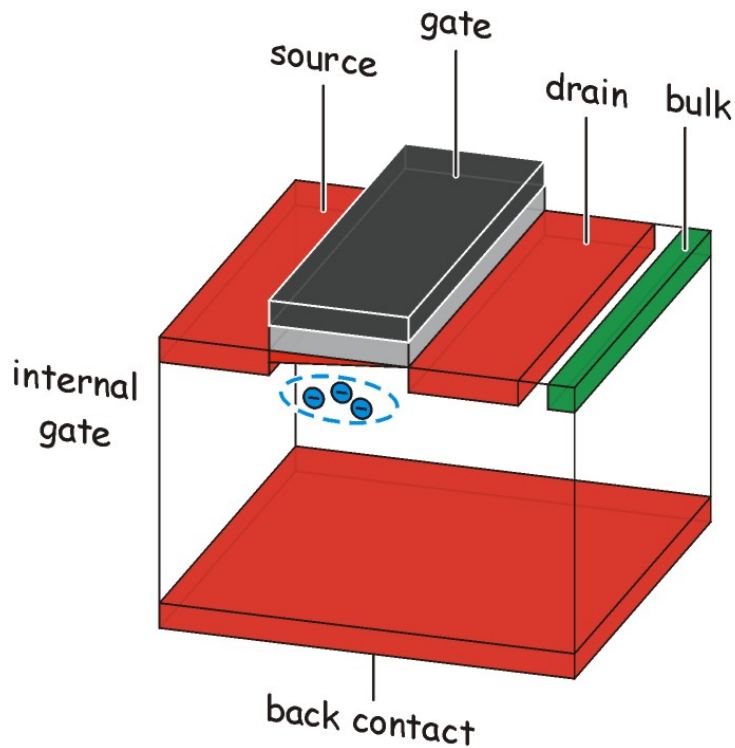


Time jitter vs. signal charge Q



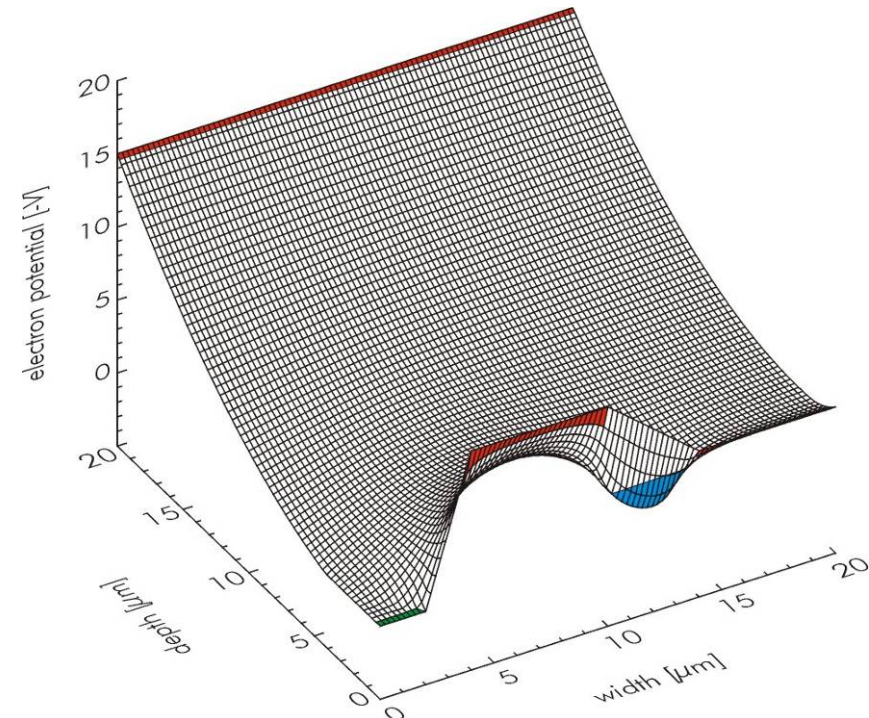
Measured time jitter @ Q=31300 el

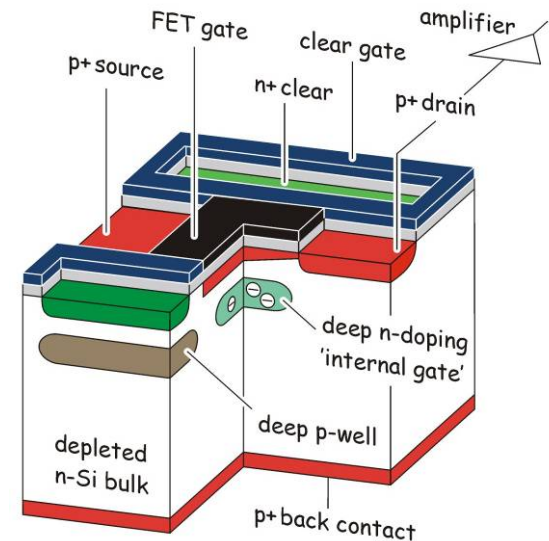
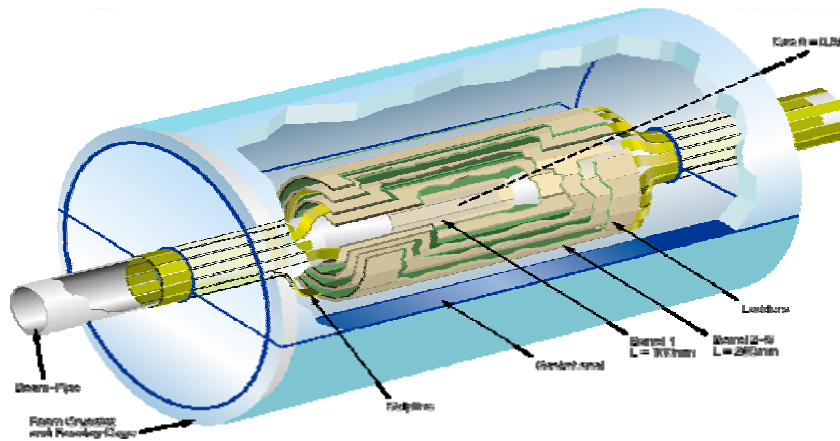
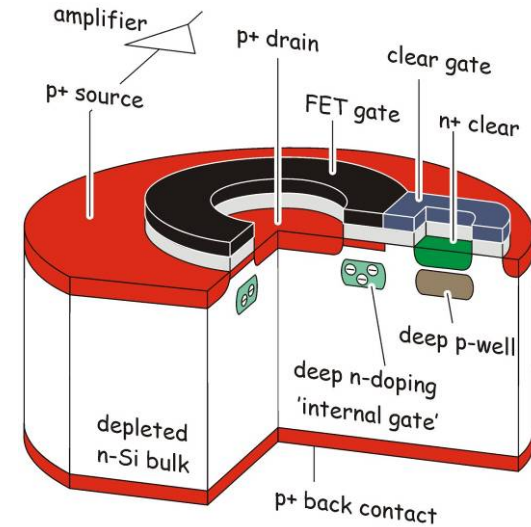
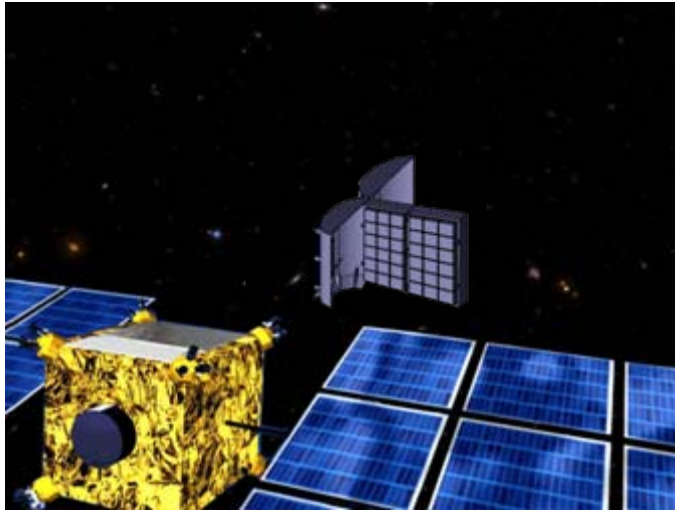
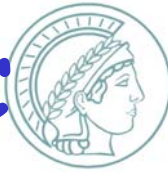




**1 electron increase current
by 0.3 nA to 1 nA**

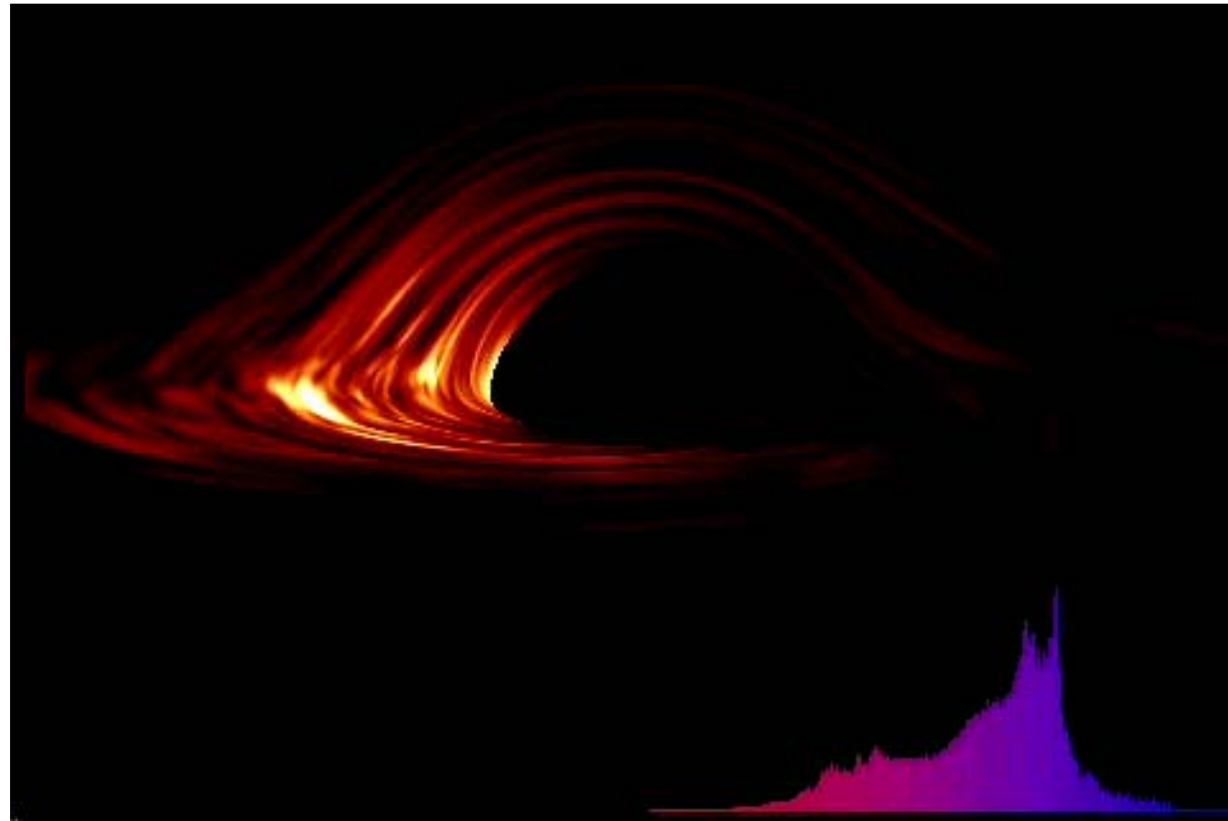
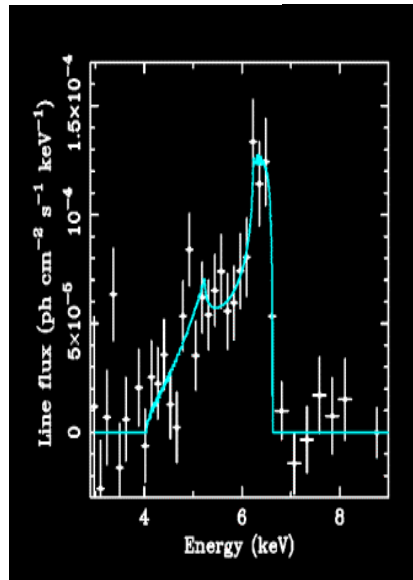
**electrons stored in the internal
gate increase source-drain current**







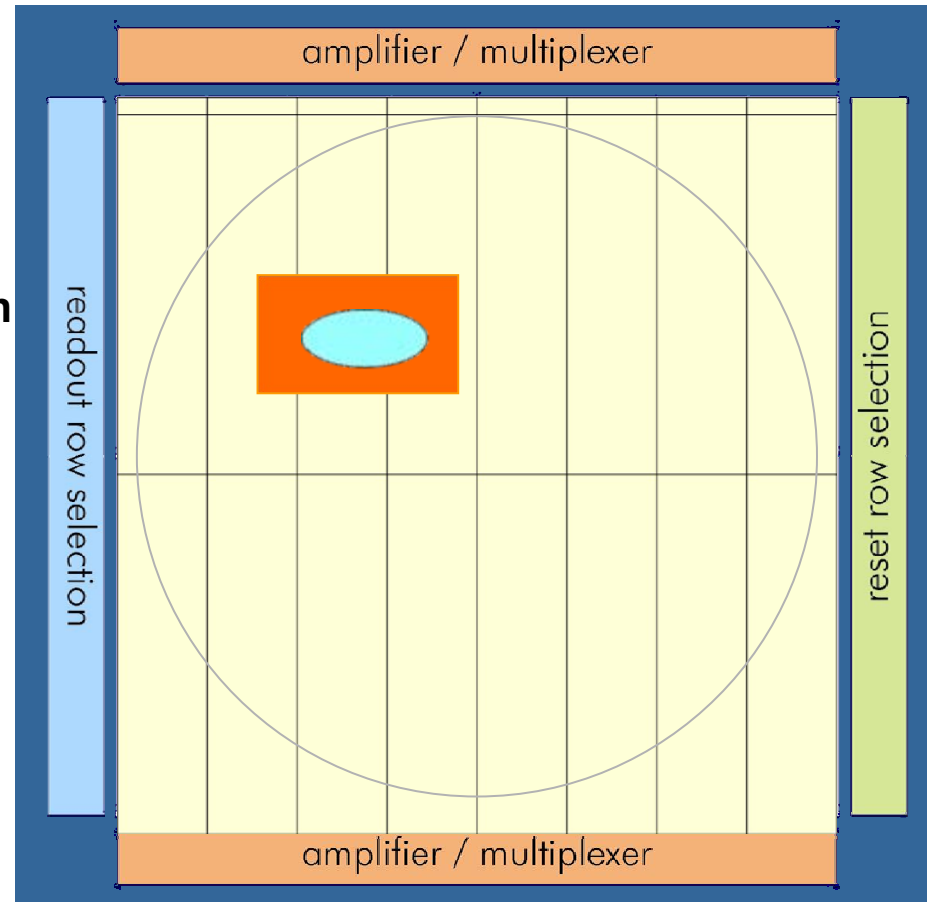
ASCA's and
XMM's relativistic
Fe-line
Tanaka et al. 1995



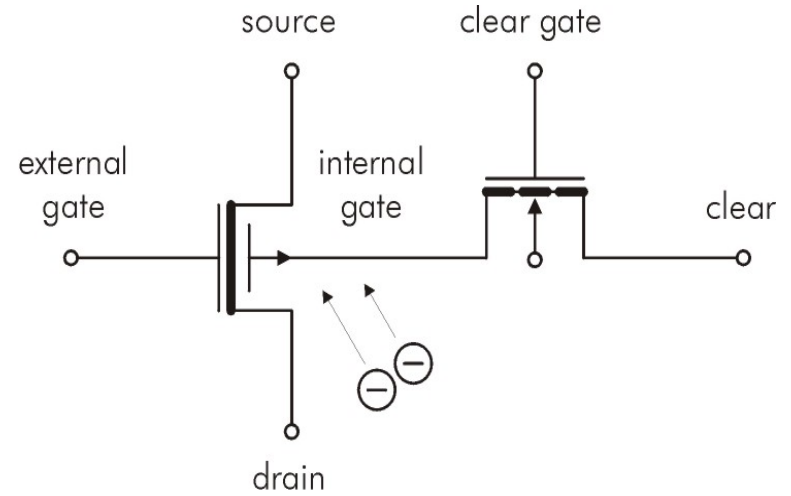
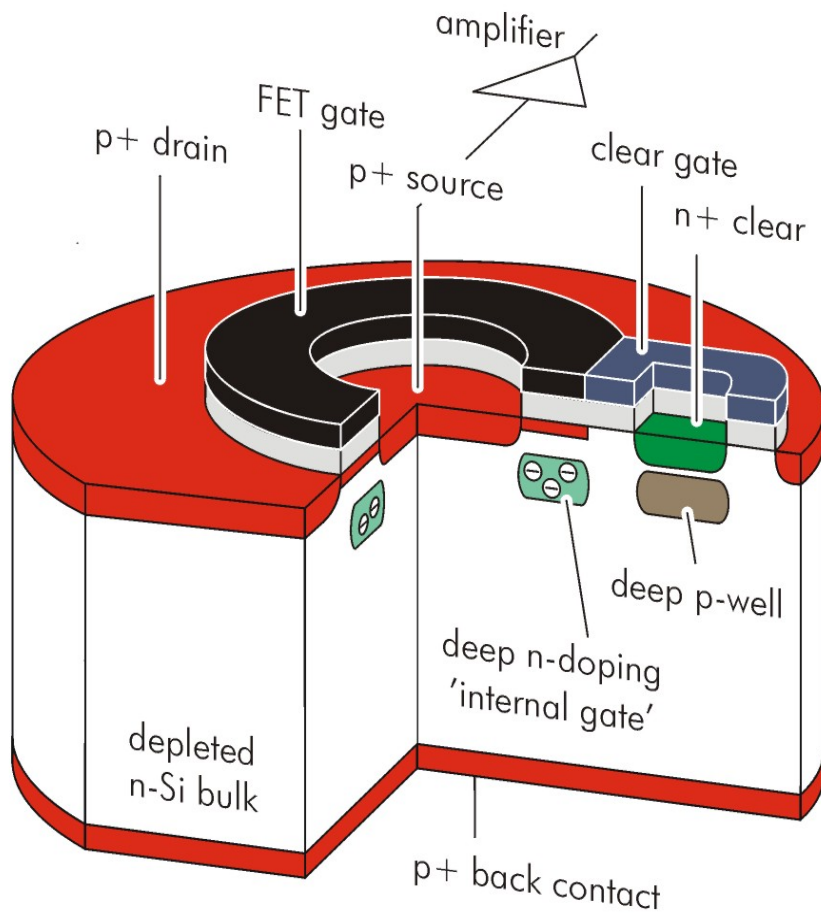
courtesy of Chris Reynolds

DEPFETs for the XEUS WFI

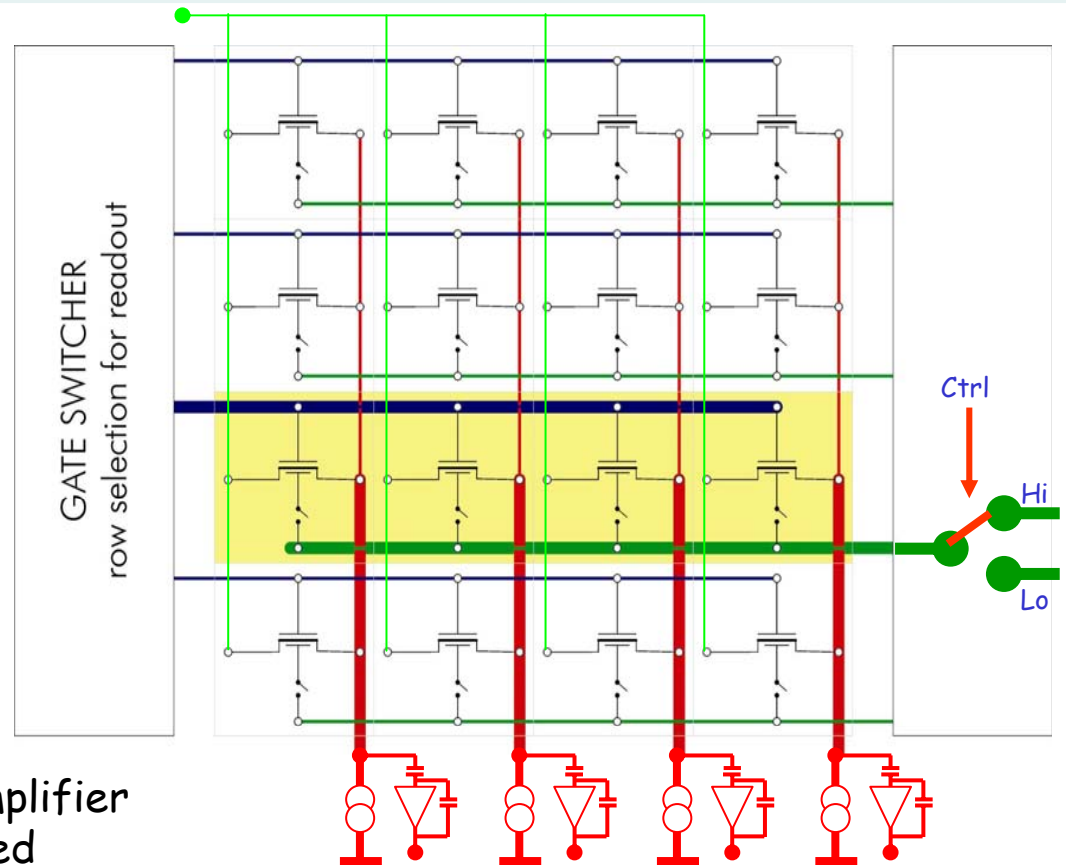
1. Flexible operating modes
2. small power dissipation (less than 2 W)
3. Fano limited energy resolution from 0.3 keV to 30 keV
4. Spatial resolution better than $15 \mu\text{m}$ @ $100 \mu\text{m}$ pixel size
5. Homogeneous radiation entrance window
6. Intrinsic radiation hardness, no charge transfer needed
7. ENC can be lowered to less than $1 e^-$ rms with NDR
8. Optical "Blocking Filter" can be directly integrated
9. Operation at "warm temperatures", e.g. -40°C



Circular DEPMOSFET pixels



- Global drain contact
- Sources connected column-wise
- Gate, Clear & Cleargate connected row-wise
- Source follower readout: Column biased by current source



CAMEX 64 G:

64 channel low noise voltage amplifier
8-fold CDS-filter and integrated sequencer

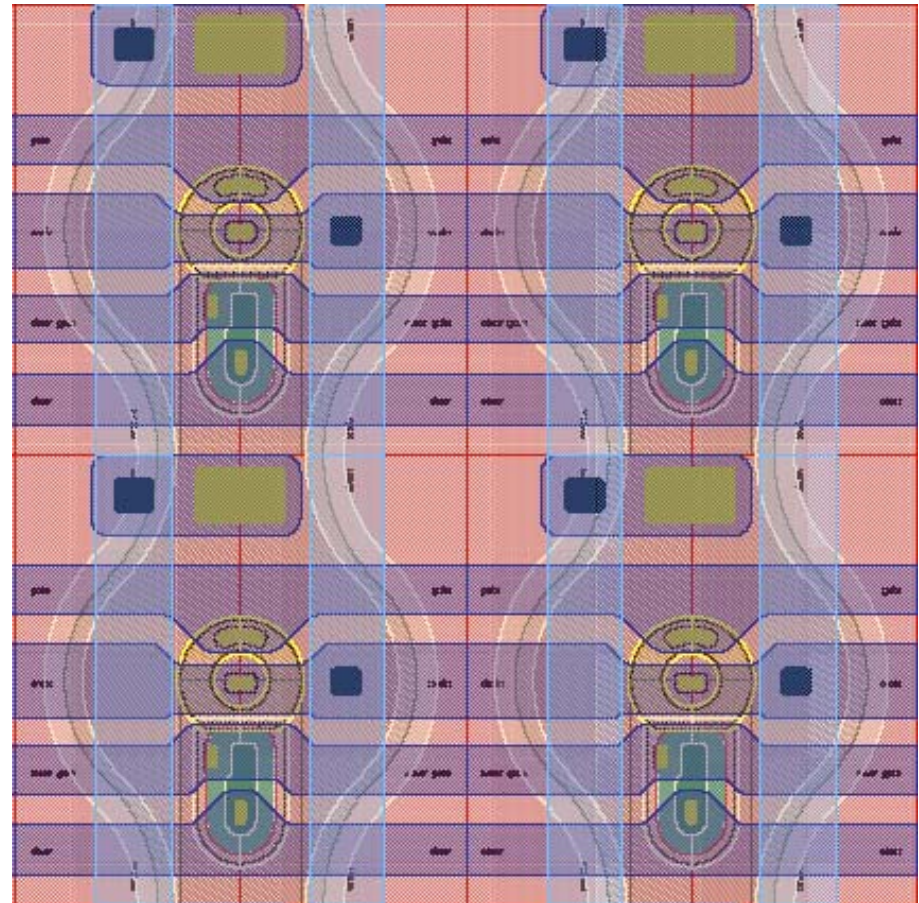
Switcher II:

Control chip with 64 channels a 2 ports & integrated sequencer
AMS high voltage CMOS process (up to 20 V)

- **STD: 45 μm gate circumference / 5 μm Gate length**

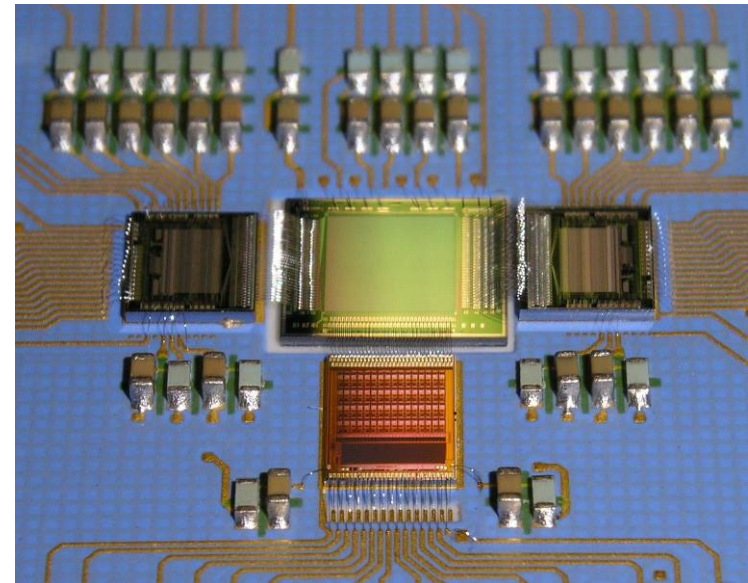
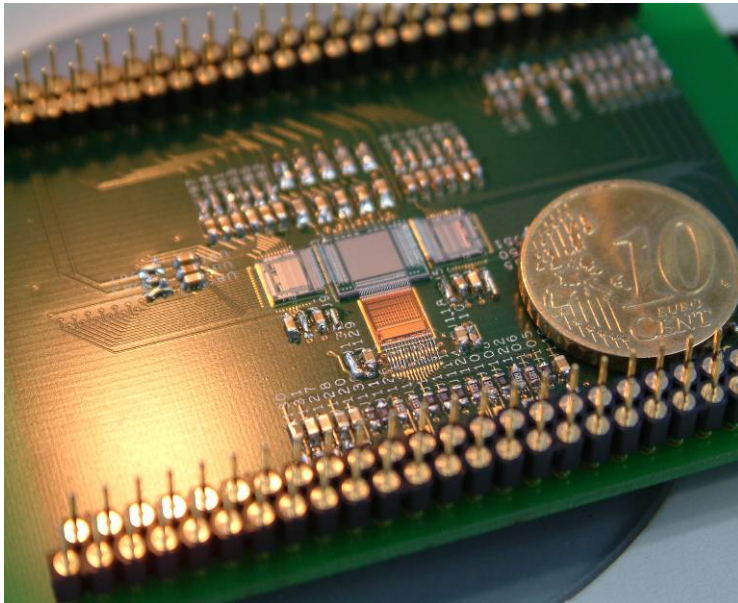
All structures with 2 polysilicon and 2 metal layers

Structures of this type homogeneous and defect free



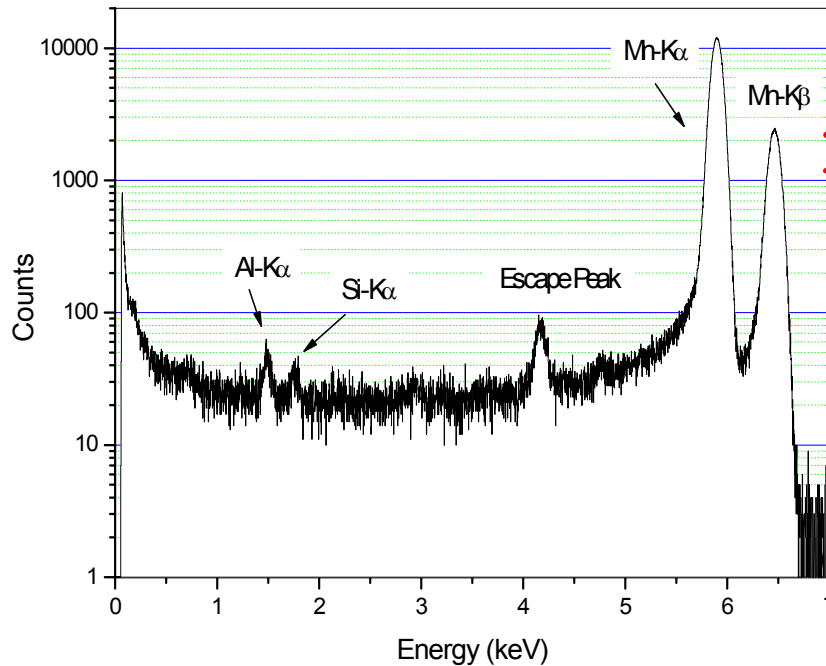
Prototype matrices

- 64 x 64 pixel arrays with $75 \times 75 \mu\text{m}^2$ pixel size
 - Complete set of control & readout electronics
 - 2 kinds of hybrids: PCB & Ceramic
 - PCB for pre-testing and structure selection
 - Ceramic for high-performance tests at low temperature
 - Modular, PC based and scalable readout system for test & evaluation
- PCB type Hybrid



➤ Ceramic Hybrid

Energy resolution of DEPMOSFET arrays

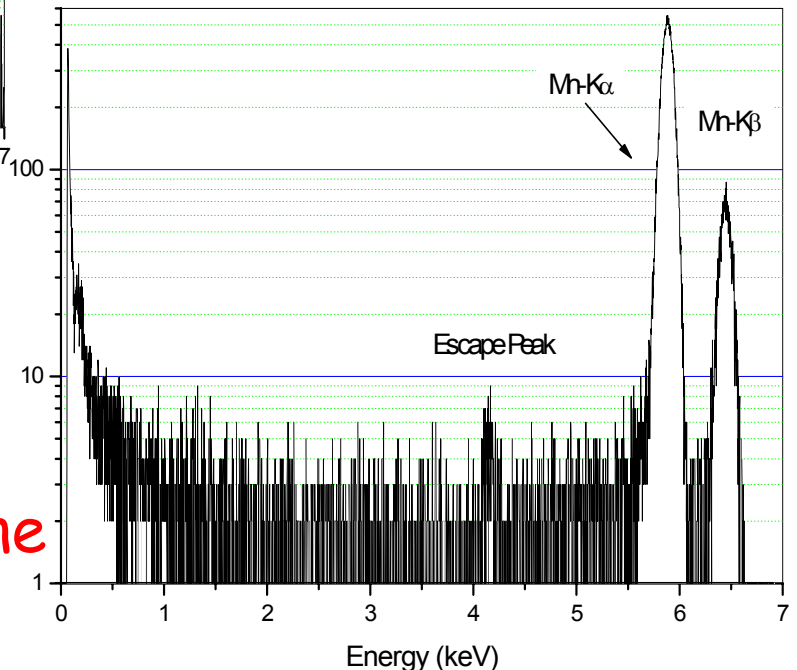


"Frontside" illumination:
Source illuminates electronic side

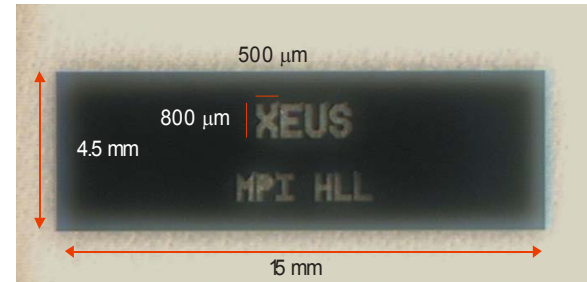
Energy resolution:
131 eV FWHM @ Mn-K α Line
corresponding to 6.4 e⁻ ENC

Energy resolution:
133 eV FWHM @ Mn-K α Line
corresponding to 6.9 e⁻ ENC

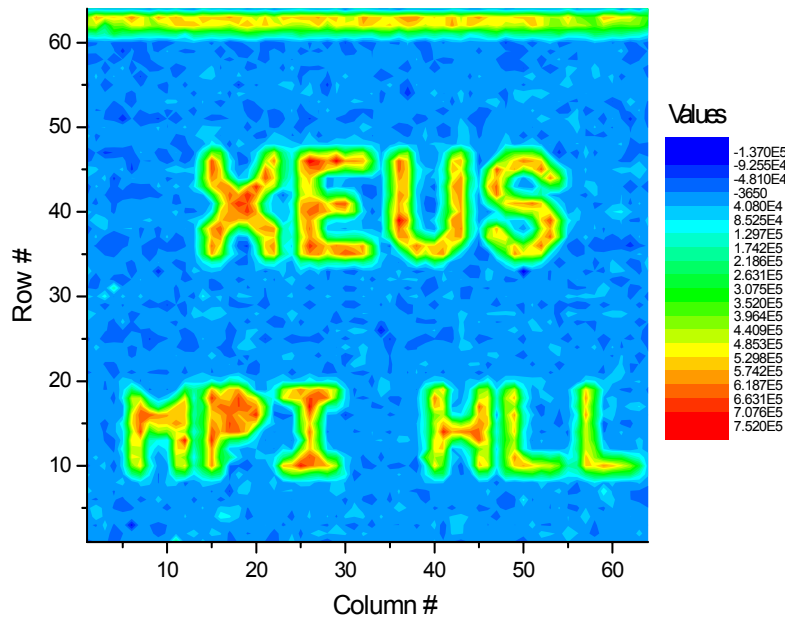
"Backside" illumination:
Source on top of entrance window



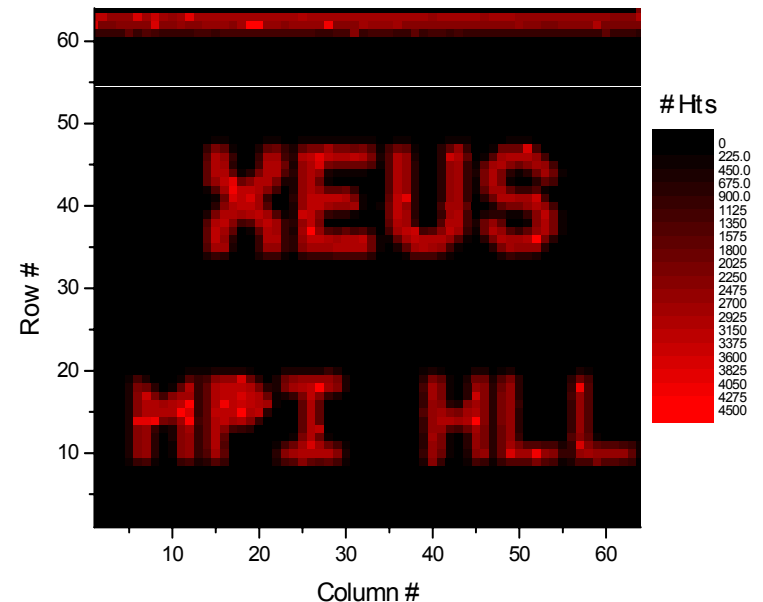
- Illumination from backside
- Baffle: 300 μm thick silicon
- Minimal structure size: 150 μm
- Exposure ca. 100000 frames



- Contour plot from ADU maps

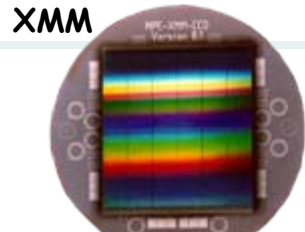


- Hitmap with 100 ADU threshold

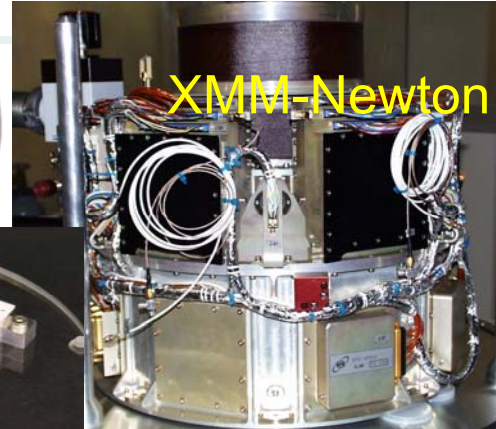




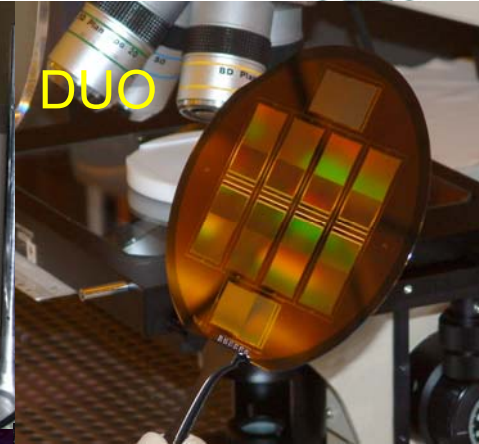
ROSAT



XMM



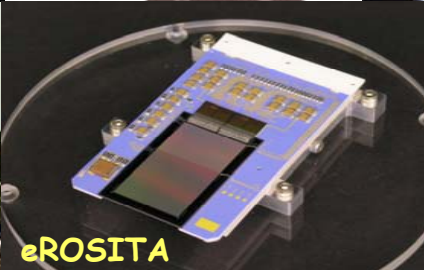
XMM-Newton



DUO



CGRO



eROSITA



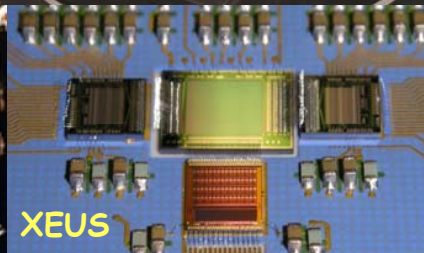
ABRIXAS



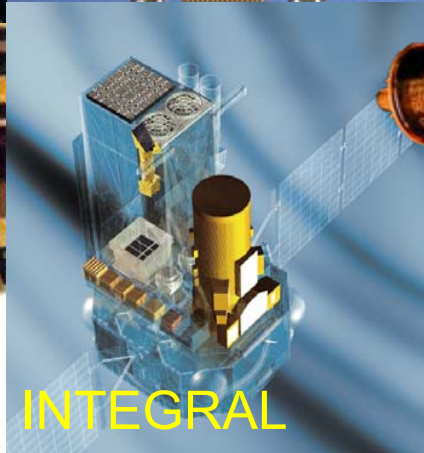
ROSITA



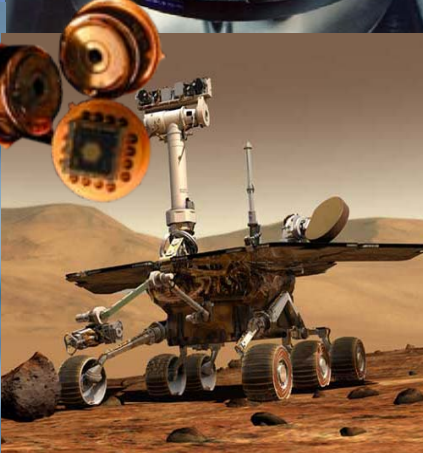
Chandra/LETG



XEUS



INTEGRAL



XEUS